# **Compal Confidential**

# **VAWGA/B Schematics Document**

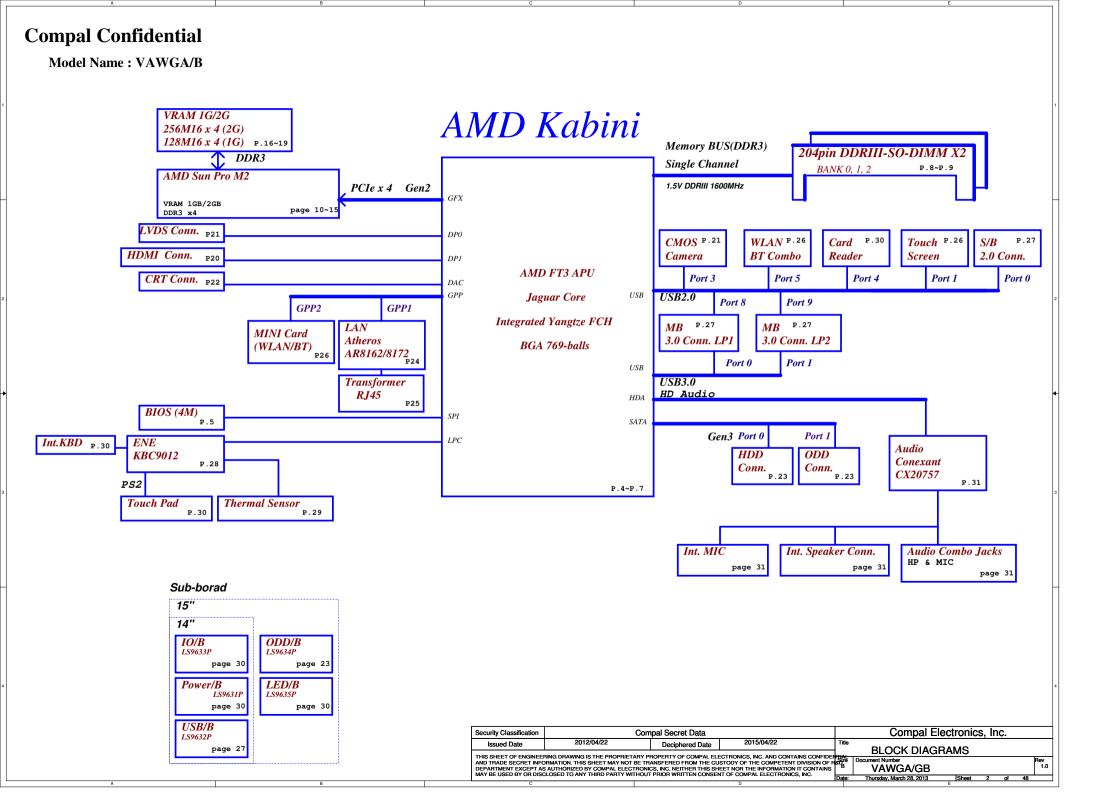
AMD "Kabini" Platform

**AMD 25W APU With Jaguar Core and Integrated Yangtze FCH + ATI Sun** 

LA-9911P REV: 1.0

2013-04-01

Security Classification	cation Compal Secret Data				Compal Electronics, Inc.		
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### **Voltage Rails**

Description

Core voltage for APU

Adapter power supply (19V)

Voltage for On-die VGA of APU

0.95-1.2V switched power rail

0.95-1.2V switched power rail

3.3V always on power rail

1.8V always on power rail

0.95V always on power rail

0.95V switched power rail

1.5V switched power rail

5V always on power rail

5V switched power rail

RTC power

VSB always on power rail

1.5V power rail for APU and DDR

3.3V switched power rail for VGA

1.8V switched power rail for VGA

1.5V switched power rail for VGA

0.95V switched power rail for VGA

0.75V switched power rail for DDR terminator

3.3V switched power rail

1.8V switched power rail

AC or battery power rail for power circuit.

Power Plane

+APU CORE

+VGA\_CORE

+VDDCI

+3VALW

+1.8VALW

+0.95VALW

+0.95VS

+1.5V

+1.5VS

+3VGS

+1.8VGS

+1.5VGS

+0.95VGS

+5VALW

+5VS

+VSB

+RTC APU

+0.75VS

+3VS

+1.8VS

+APU CORE NB

BOARD	ID Table
-------	----------

Board ID	PCB Revision
0	MP
1	PVT
2	DVT
3	EVT
4	
5	
6	
7	

STATE	SLP_S3#	SLP_S5#	+VALW	+V	+VS	Clock
Full ON	HIGH	HIGH	ON	ON	ON	ON
S1 (Power On Suspend)	HIGH	HIGH	ON	ON	ON	LOW
S3 (Suspend to RAM)	HIGH	HIGH	ON	ON	OFF	OFF
S4 (Suspend to Disk)	LOW	HIGH	ON	OFF	OFF	OFF
S5 (Soft OFF)	LOW	LOW	ON	OFF	OFF	OFF

#### Board ID / SKU ID Table for AD channel

#### **USB OC MAPPING**

OC#	USB Port							
0	USB20 port0							
1	USB20 port1,2,8,9	USB30 port0,1						
2								
3								

BTO Item

Vcc	3.3V +/- 5%			
R1562	100K +/- 5%			
Board ID	R1564	$V_{AD\_BID}$ min	V <sub>AD_BID</sub> typ	$V_{AD\_BID}$ max
0	0	0 V	0 V	0 V
1	8.2K +/- 5%	0.216 V	0.250 V	0.289 V
2	18K +/- 5%	0.436 V	0.503 V	0.538 V
3	33K +/- 5%	0.712 V	0.819 V	0.875 V
4	56K +/- 5%	1.036 V	1.185 V	1.264 V
5	100K +/- 5%	1.453 V	1.650 V	1.759 V
6	200K +/- 5%	1.935 V	2.200 V	2.341 V
7	NC	2.500 V	3.300 V	3.300 V

#### **BOM Structure Table**

BOM Structure

BOM SCIUCCUIE	BIO ICEM				
A6@	A6 R3 BGA APU				
A4@	A4 R3 BGA APU				
E2@	E2 R3 BGA APU				
E1@	E1 R3 BGA APU				
E1PC@	E1 PC BGA APU				
X4@	X4 ES2 BGA APU				
X5@	X5 ES2 BGA APU				
X2@	X2 ES2 BGA APU				
EMICU@	CardReader EMI Un pop				
EMICP@	CardReadear EMI pop				
EMIUSB2RU@	Right USB2.0 port EMI un pop				
EMIUSB2RP@	Right USB2.0 port EMI pop				
USB2R@	Right USB2.0 port component				
SUN@	SUN PRO GPU (R3 compal part)				
MARS@	MARS XT GPU (R1 compal part)				
140	for 14" componect				
15@	for 15" componect				
PX@	Common VGA circuit				
CMOS@	CMOS Camera part				
HDMI@	HDMI part				
EMIGASP@	Gastube				
8162@	Ateros AR8162 LAN Chip				
8172@	Ateros AR8172 LAN Chip				
SWR@	LAN Switching mode				
LDO@	LAN LDO mode				
THERMAL@	Lenovo Thermal Sensor				
ME@	ME part				
UMA@	UMA part				
@	Unpop				
ZODD@	Zero Power ODD part				
TS@	Touch Screen				
EMIP@	EMI pop component				
EMIU@	EMI Un pop component				
ESDP@	ESD pop component				
ESDU@	ESD Un pop component				
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Monday, April 01, 2013

Rev 1.0

SMBUS Co	ntrol Ta	ble								
	SOURCE	VGA	BATT	KB9012	SODIMM	WLAN WWAN	Thermal Sensor	FCH	APU	RTD2132
SMB_EC_CK1	KB9012	Х	V	Х	Х	Х	Х	Х	Х	X
SMB_EC_DA1	+3VALW		+3VALW							
APU_SCLK0	APU	Х	Х	Х	V	V	Х	X	Х	X
APU_SDATA0	+3VS				+3VS	+ 3VS				
SMB_EC_CK2		V	X	Х	Х	Х	V		W	
SMB_EC_DA2	KB9012 +3VS	V	^	^	^	^	V	Х	V	X
	1373	+3VS					+3VS		+ 3VS	

S0

ON

S3

ON

ON

OFF

OFF

OFF

OFF

ON

OFF

ON

OFF

OFF

OFF

ON

OFF

OFF

OFF

OFF

OFF

ON

OFF

ON

ON

OFF

S5

ON

ON

OFF

OFF

OFF

OFF

OFF

OFF

ON\*

OFF

OFF

OFF

OFF OFF

OFF

OFF

OFF

OFF

ON

OFF

ON

ON

OFF

# APU PCIE PORT LIST Device LAN WLAN

#### EO CM Dured addresse EC CM Bus2 address

EC 2M B	us i address	5	EC SM Bus2 address				
Device	Address	HEX	Device	Address	HEX		
Smart Battery	0001 011X b	16H	Thermal Sensor	1001 101X b	9AH		
			SB-TSI (APU)	1001 100X b	98H		
			VGA Internal Thermal	1000 001X b	82H		

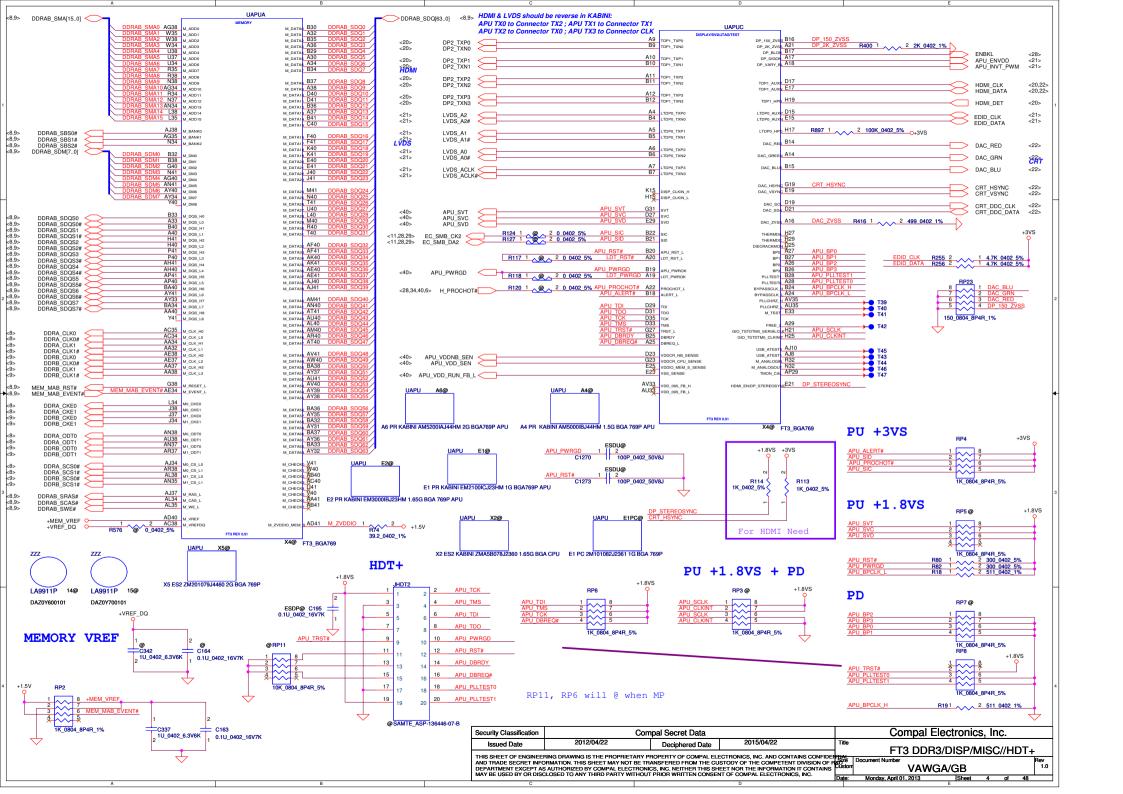
#### APU **SM Bus address**

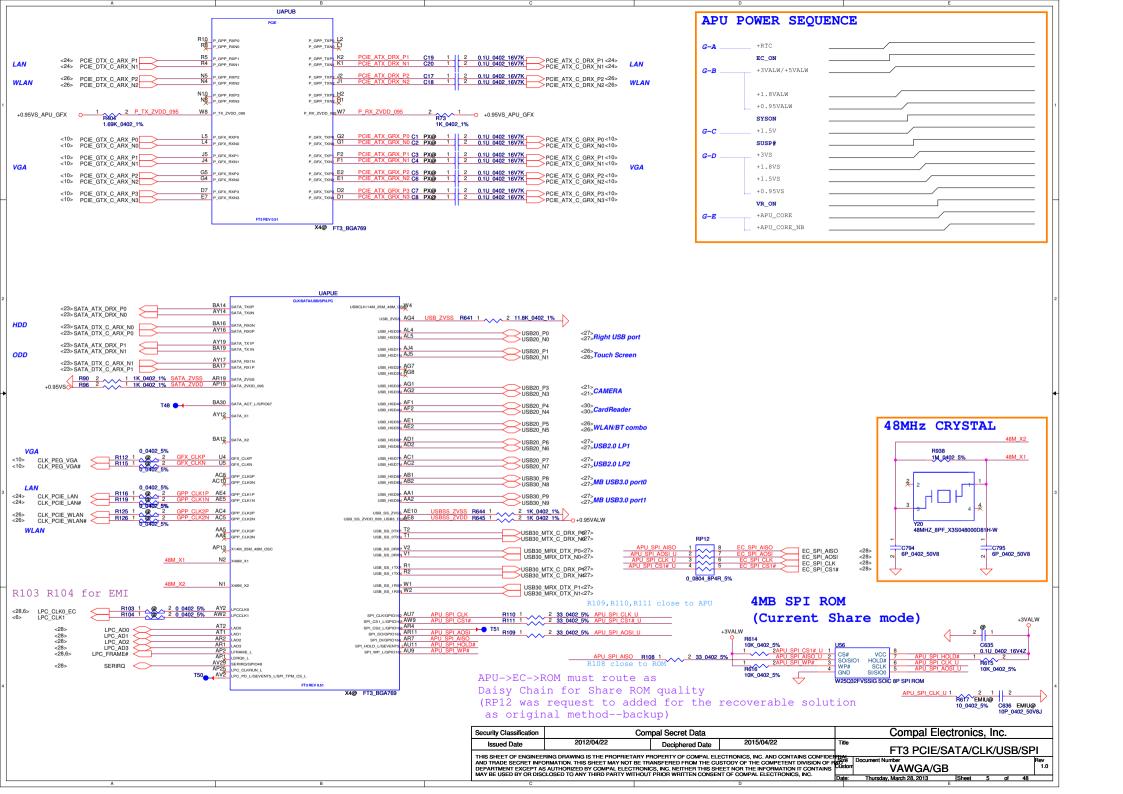
Device	Address	HEX
DDR DIMM1	1010 000Xb	A0H
DDR DIMM2	1010 001Xb	A2H

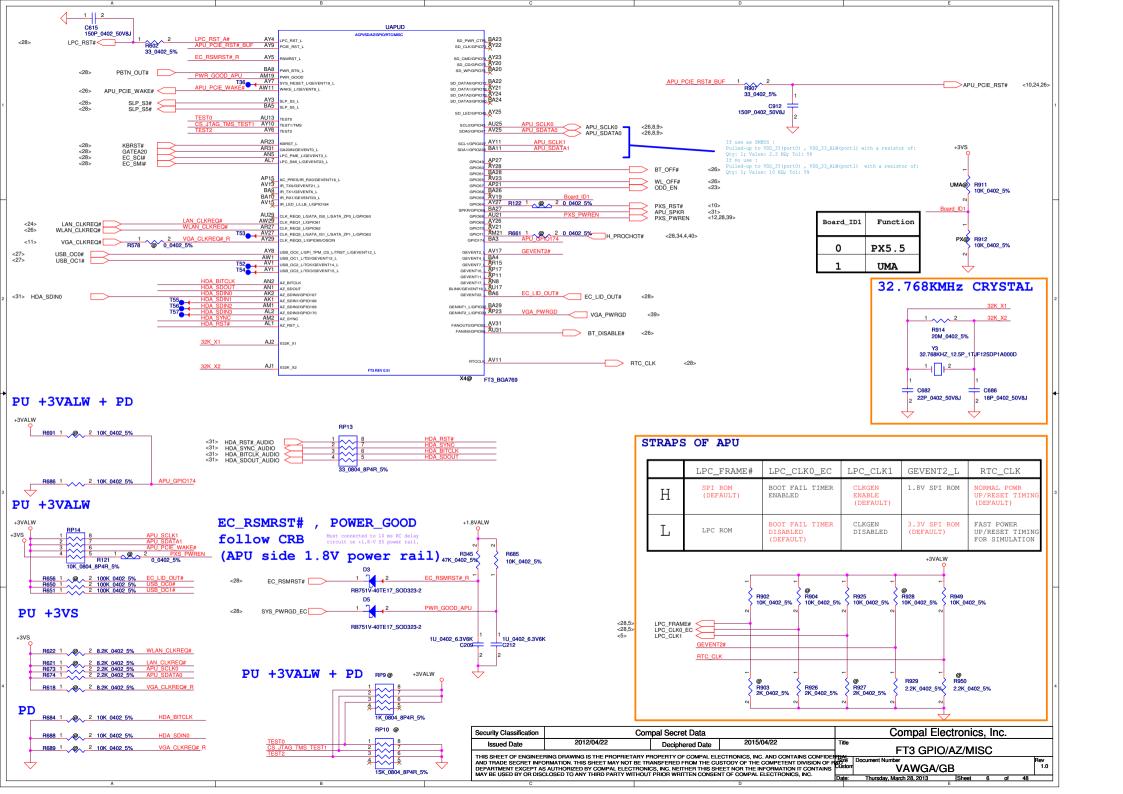
## **USB Port Table**

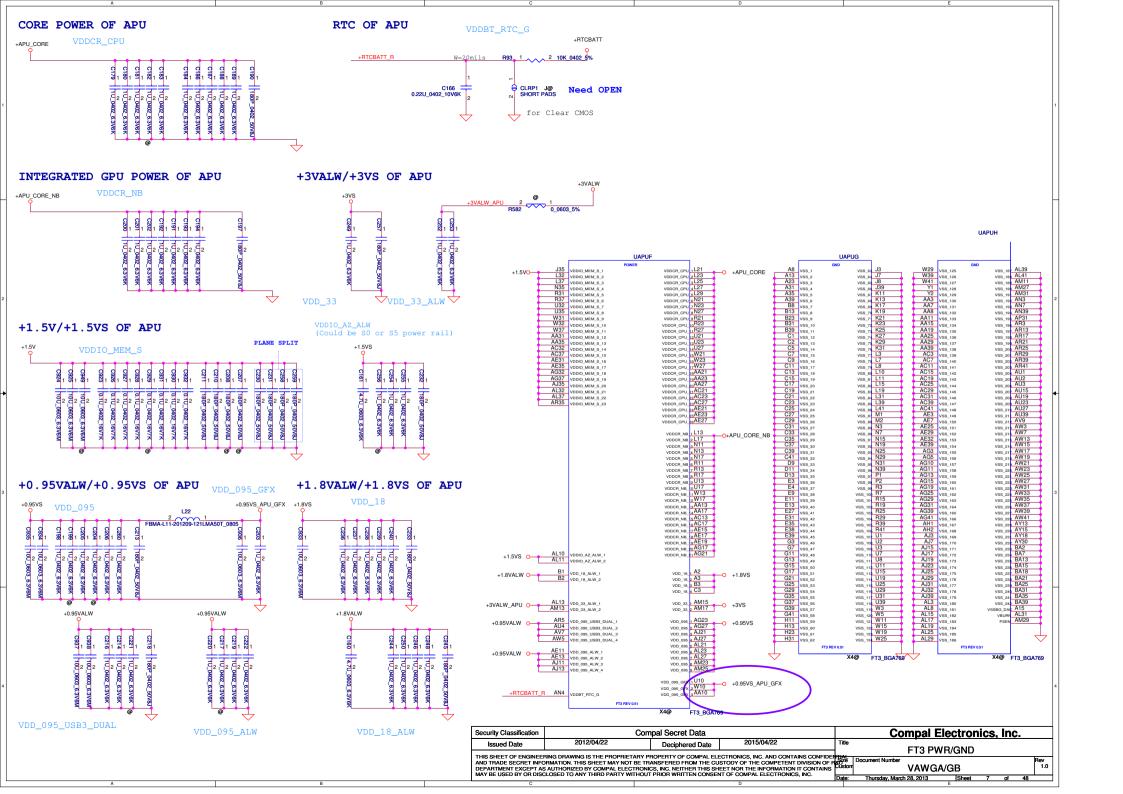
USB 2.0	USB	3.0	Port	3 External USB Port
			0	RIGHT USB
			1	Touch Screen
			2	
			3	Camera
			4	CardReader
			5	WLAN/BT Combo
			6	LEFT USB (for colay)
			7	LEFT USB (for colay)
	XHCI	0	8	LEFT USB3.0
	XHCI	1	9	LEFT USB3.0

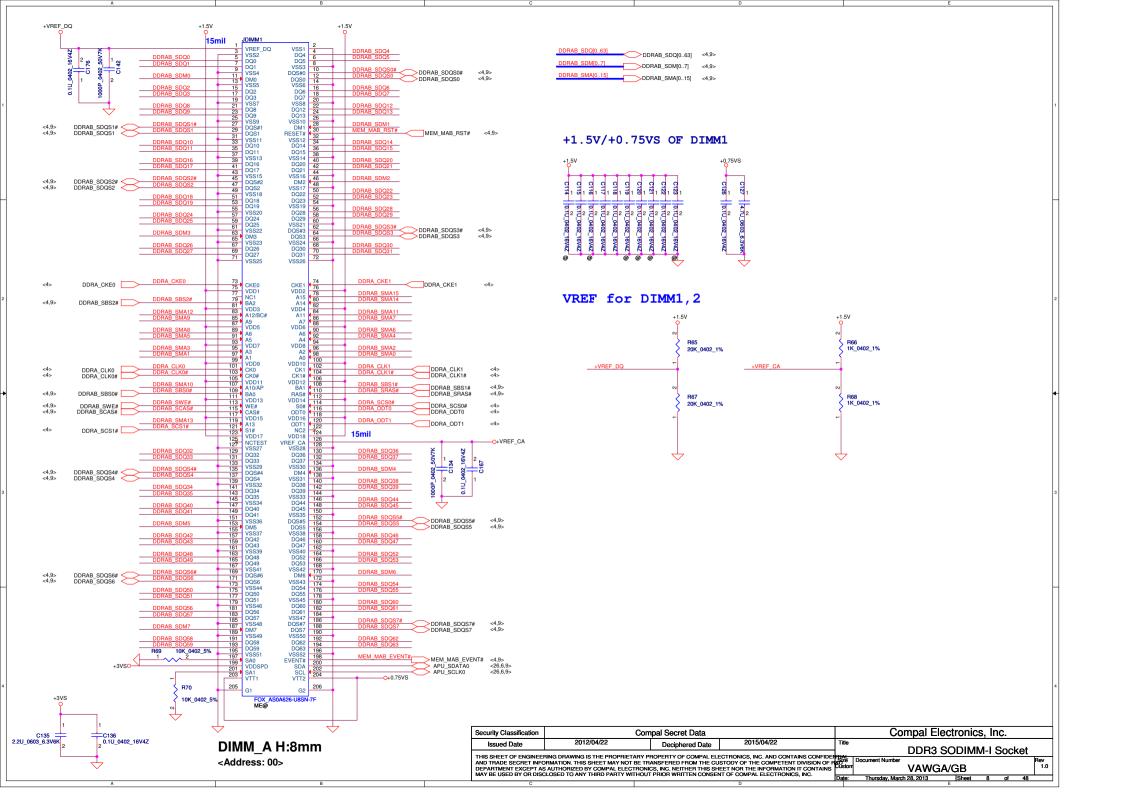
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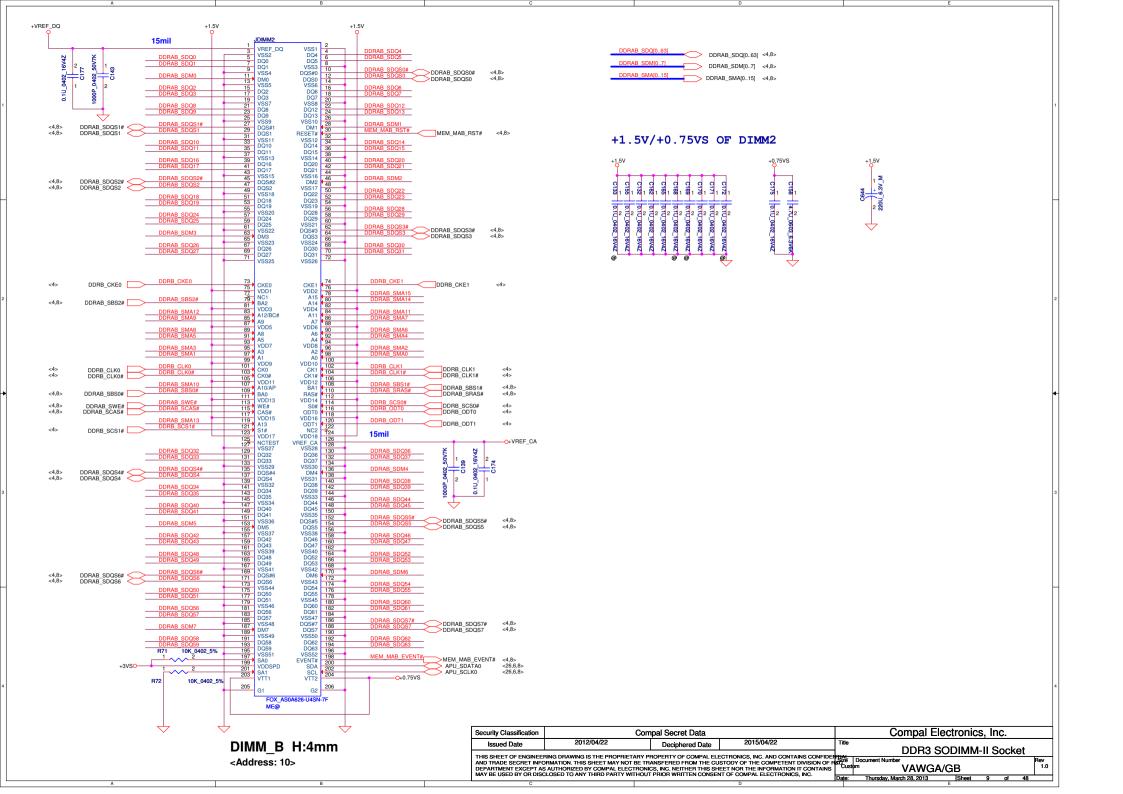


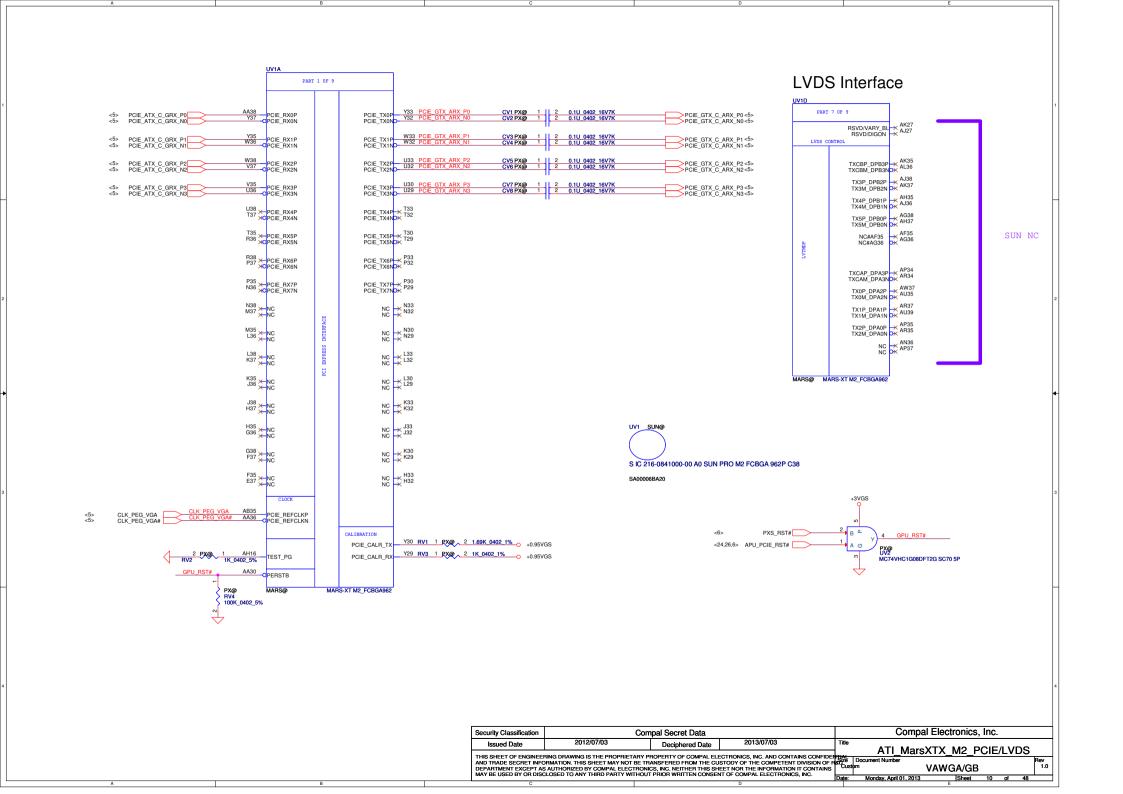


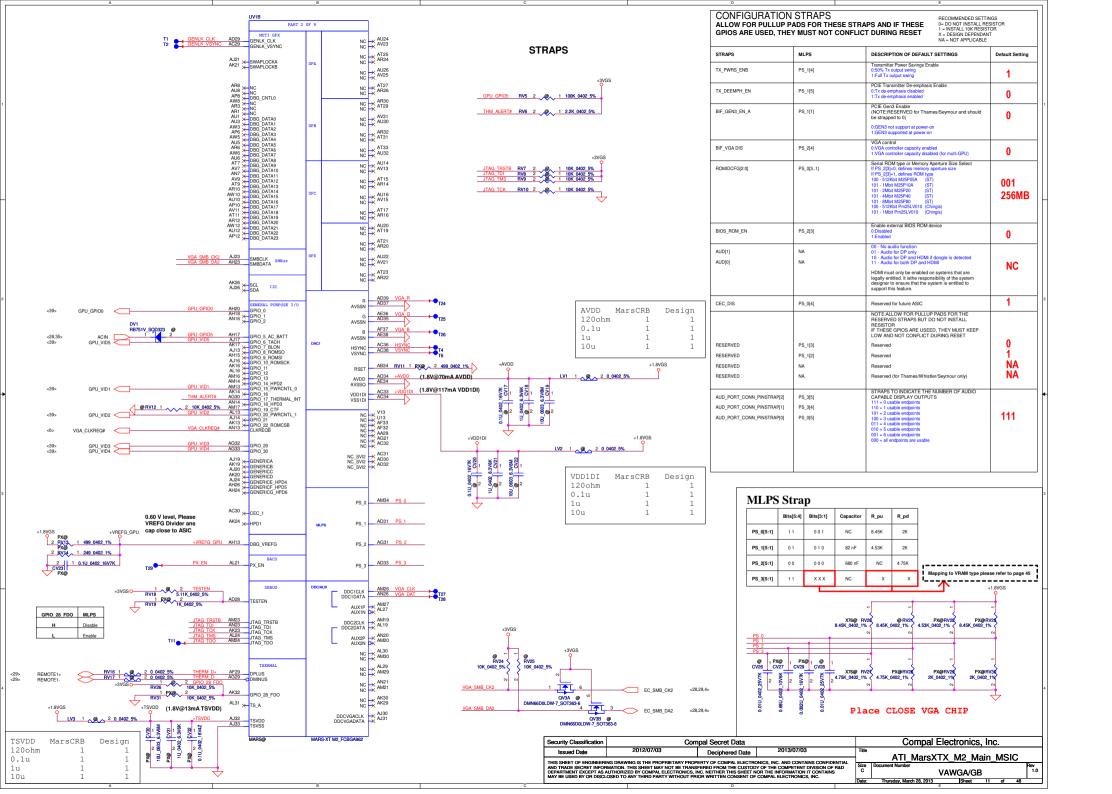


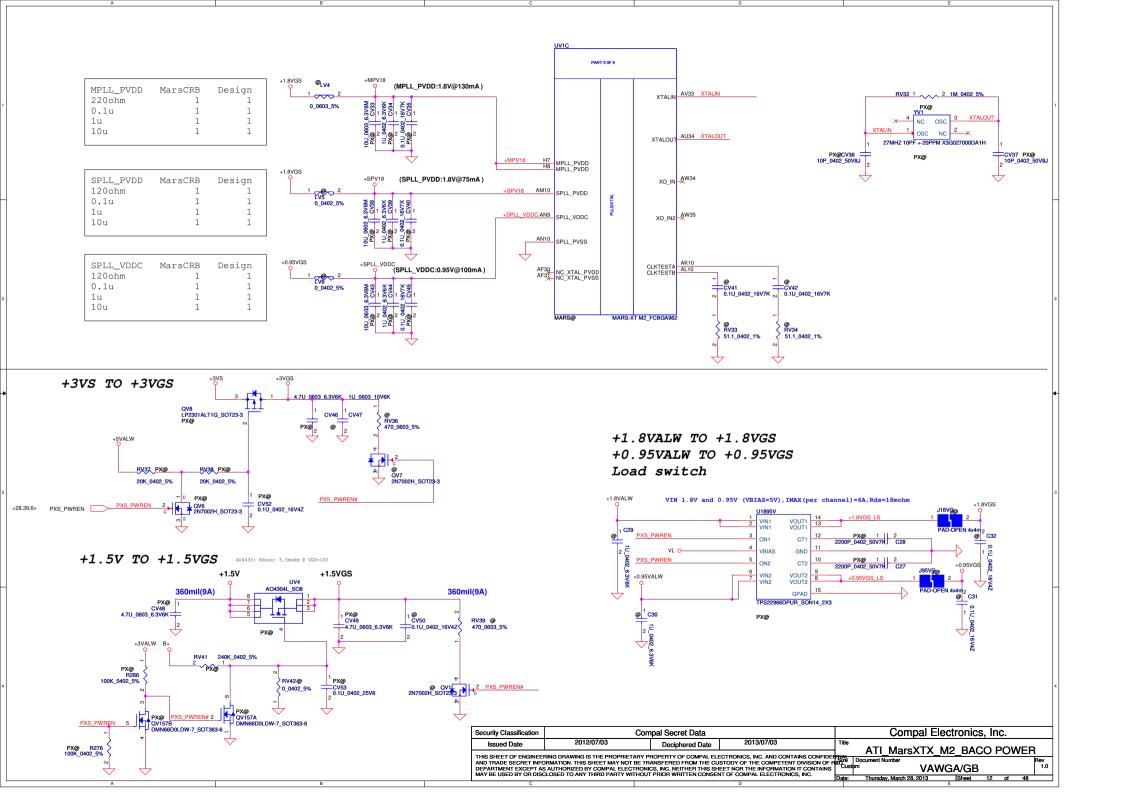


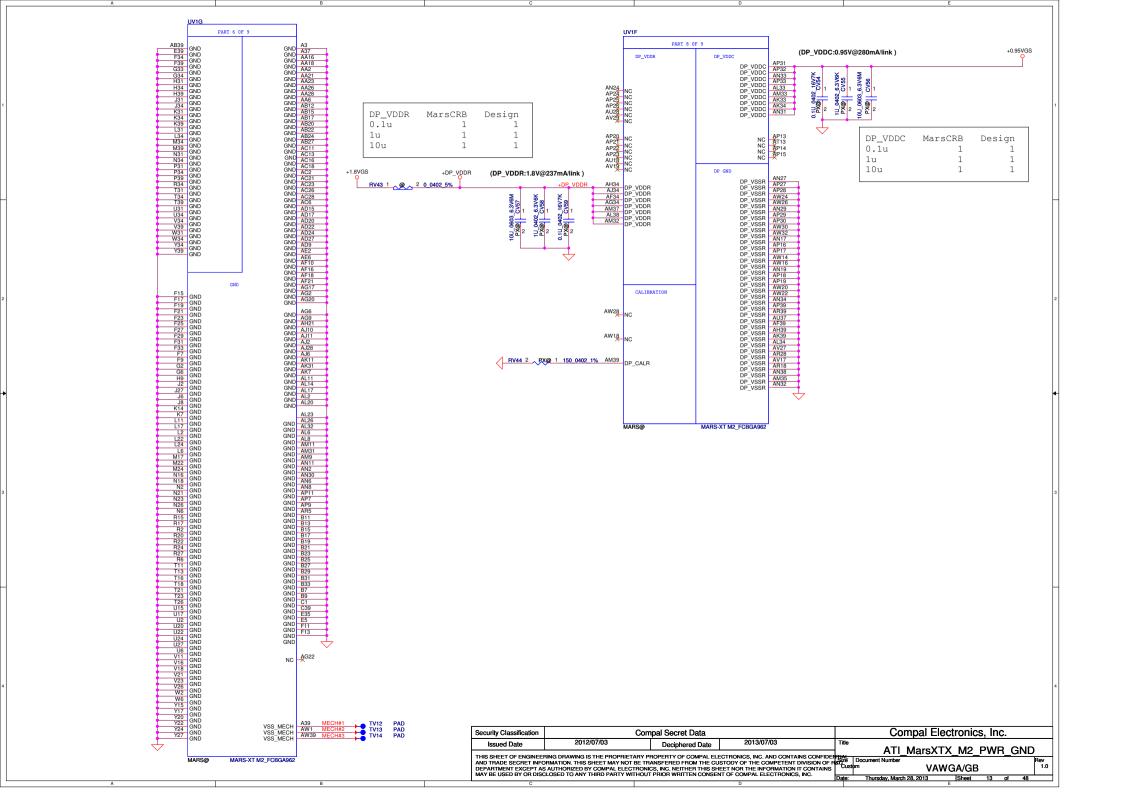


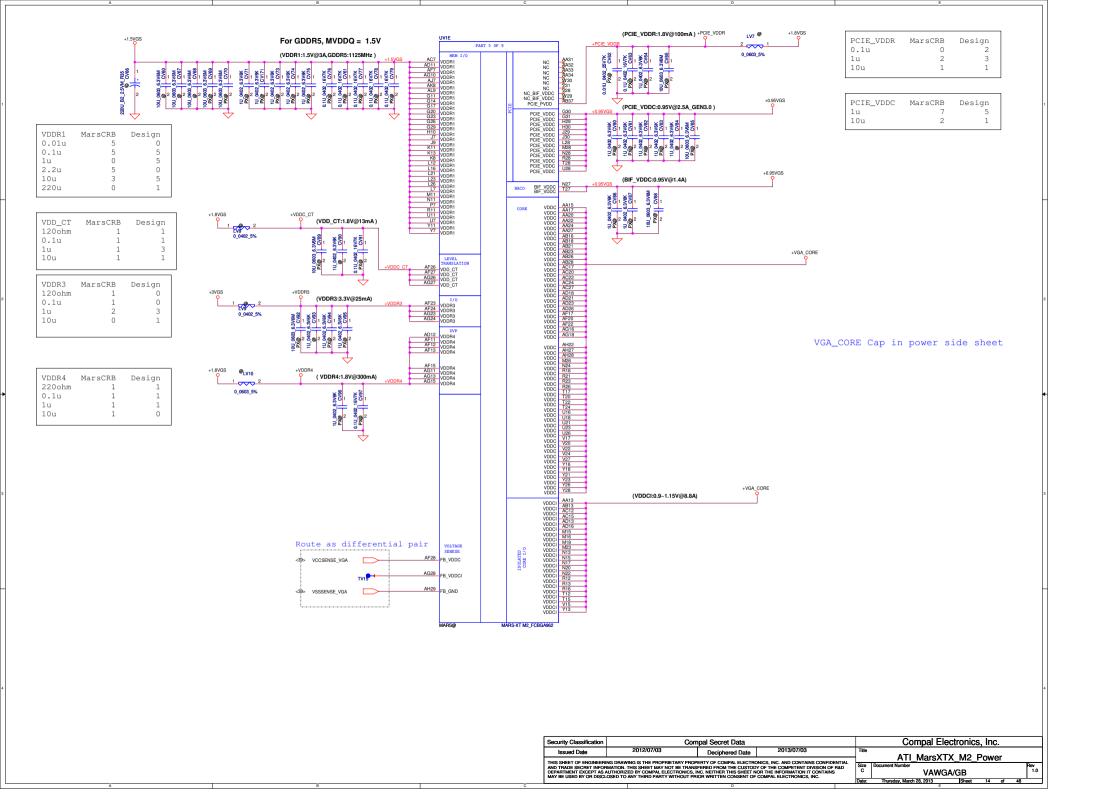


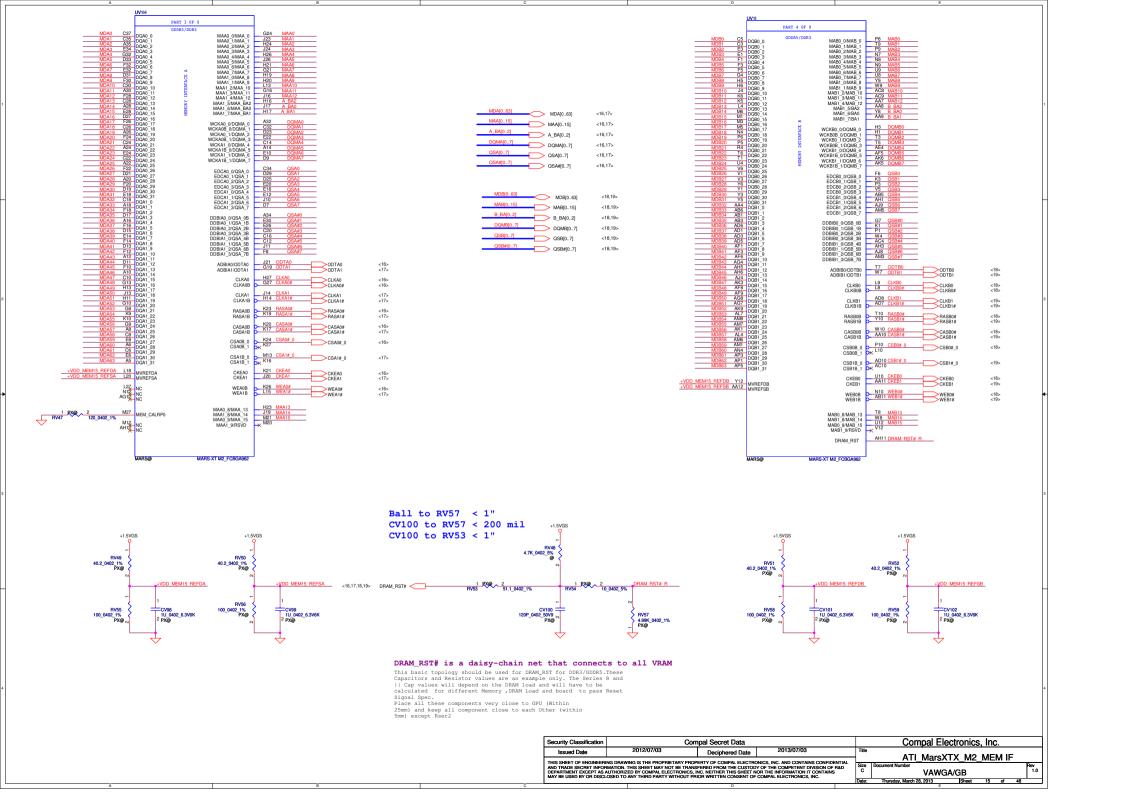


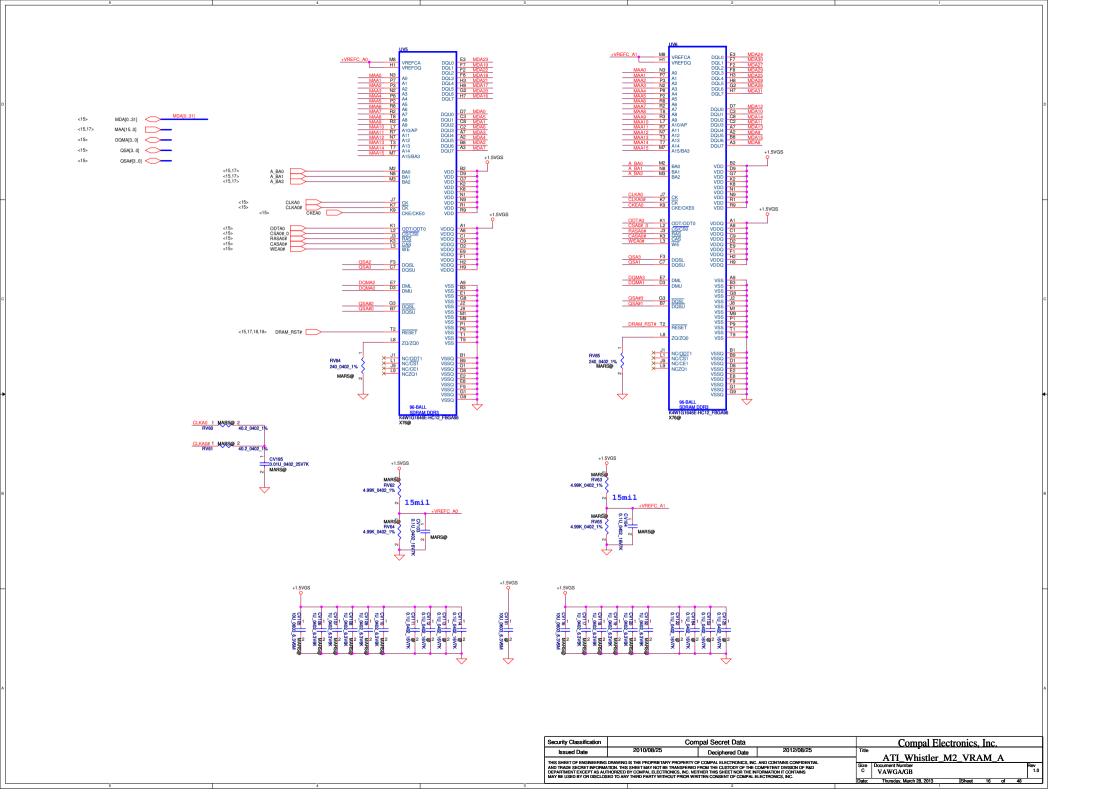


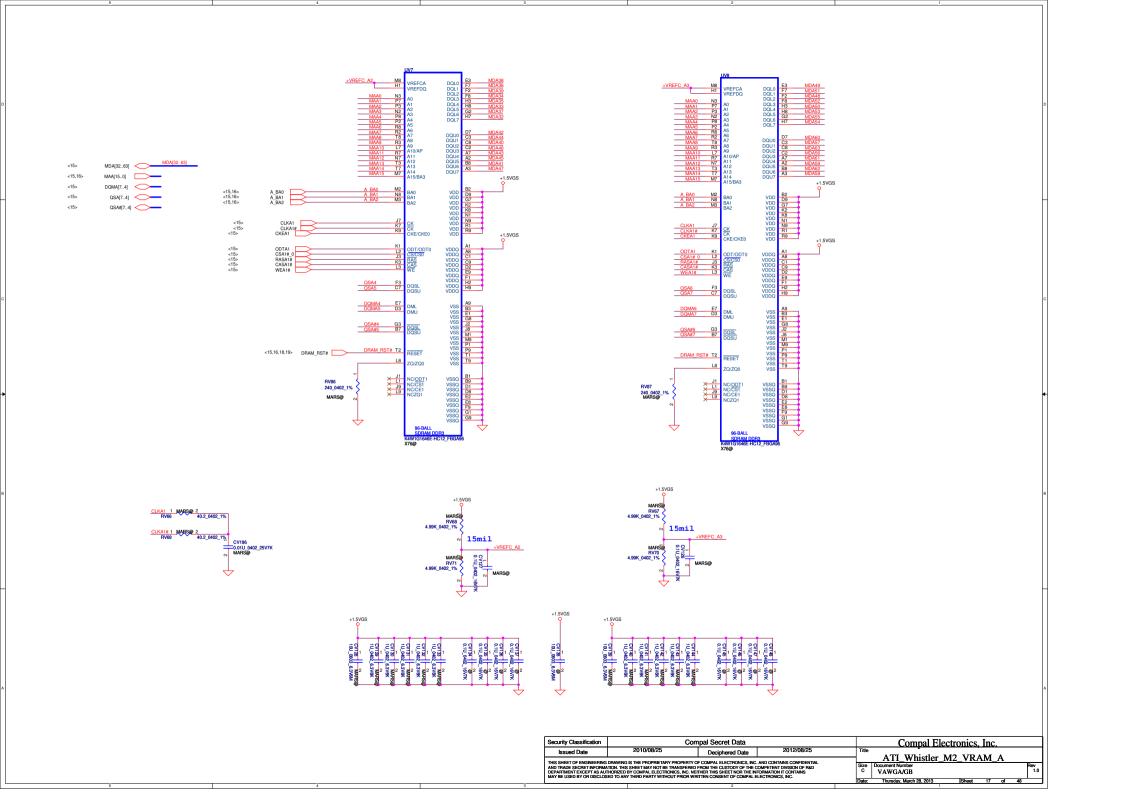


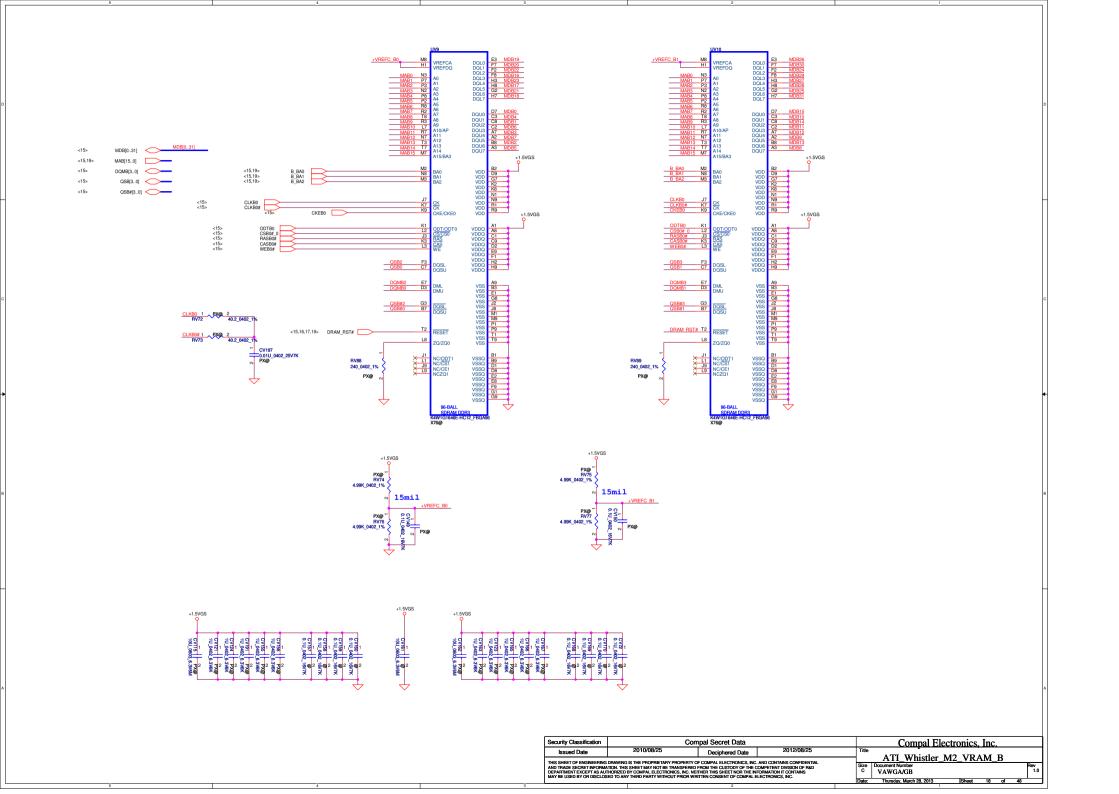


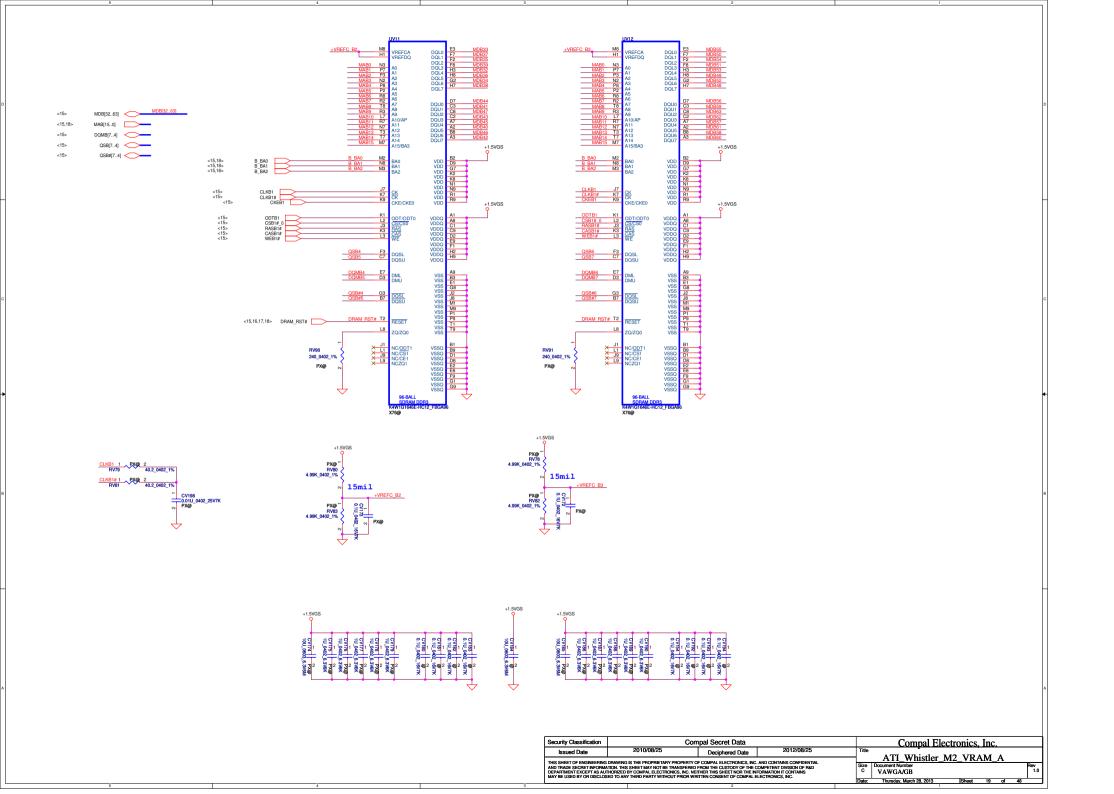


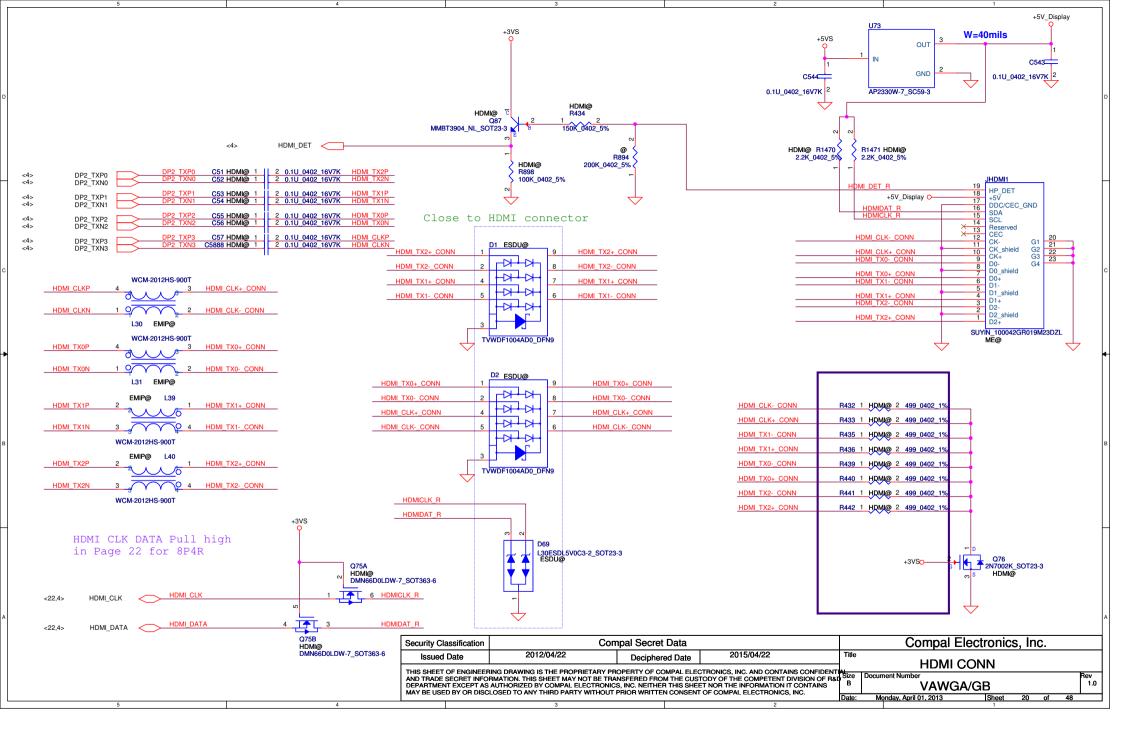


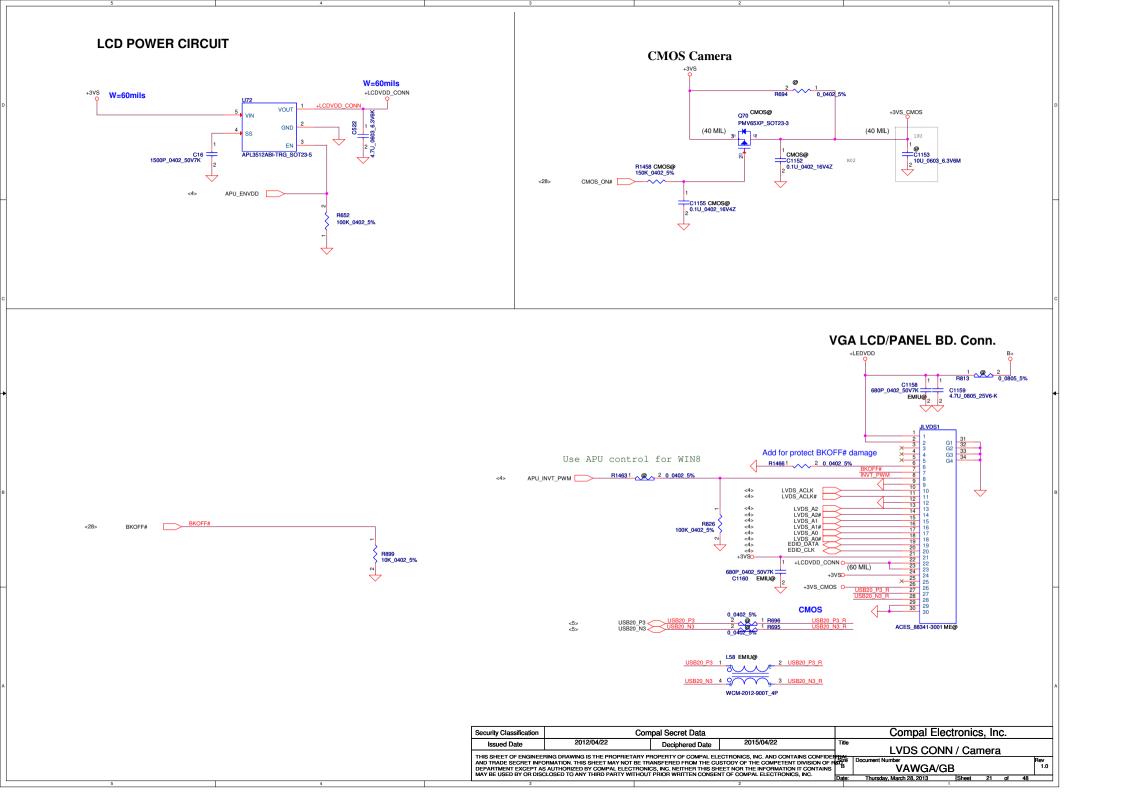


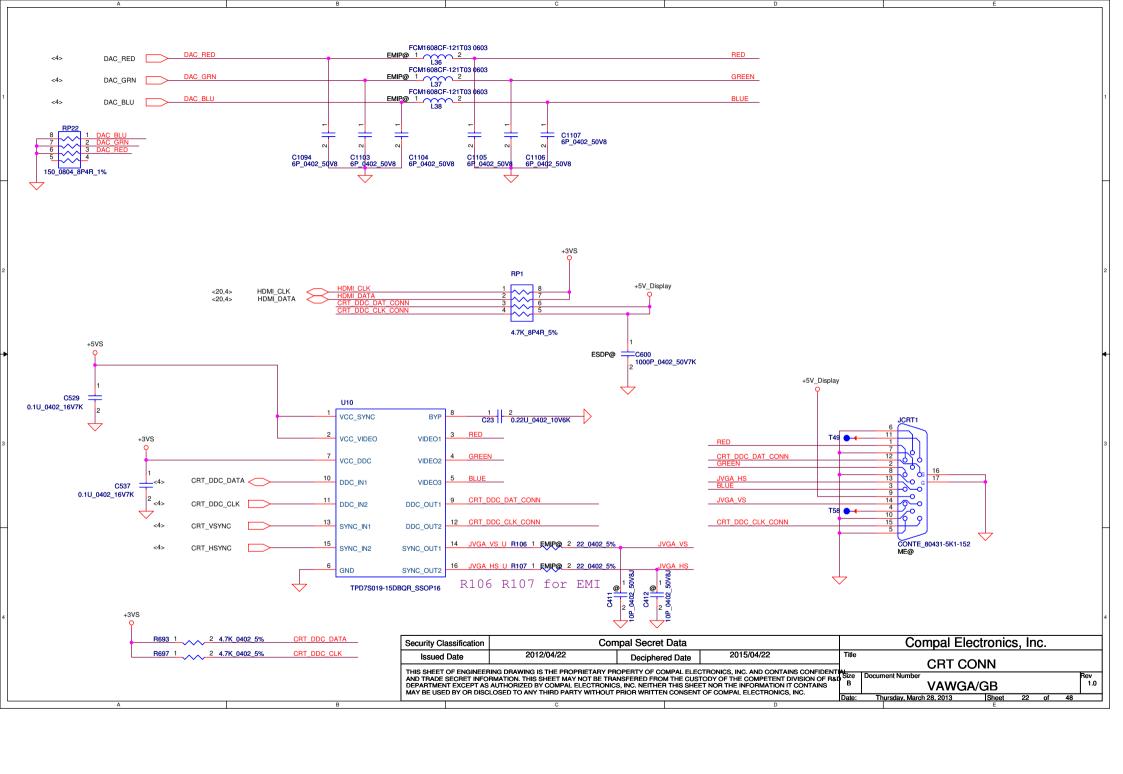


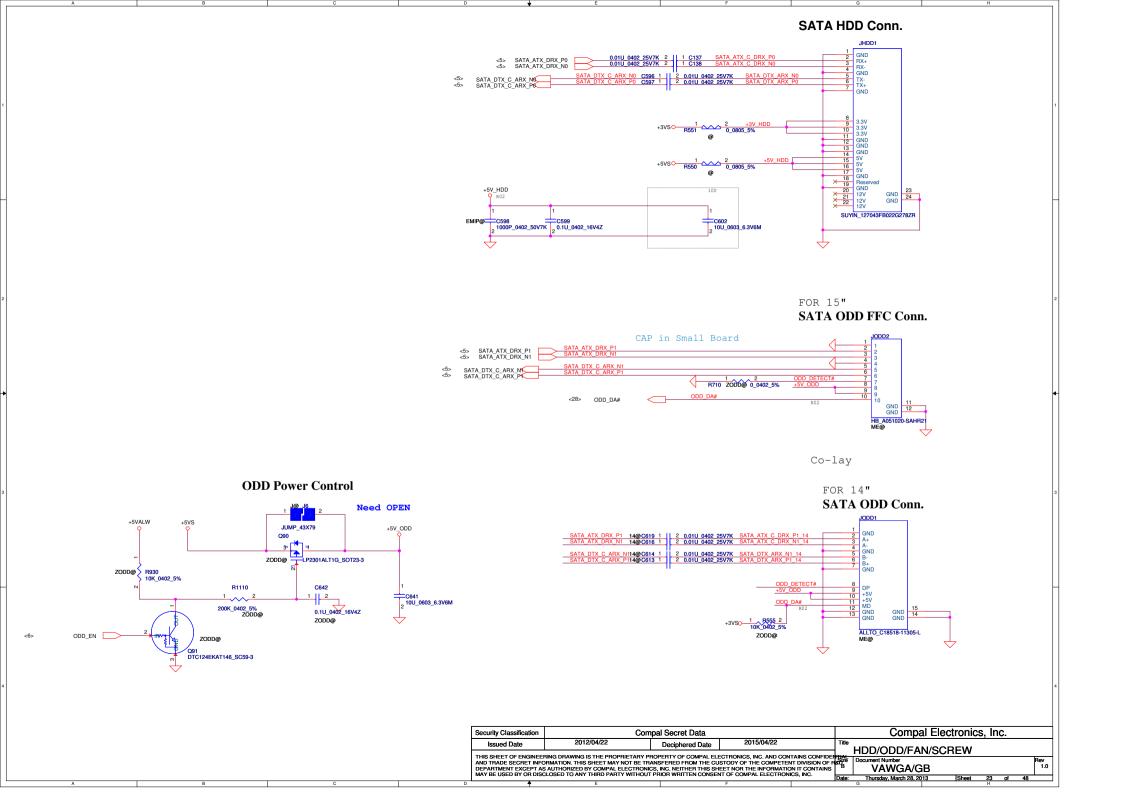


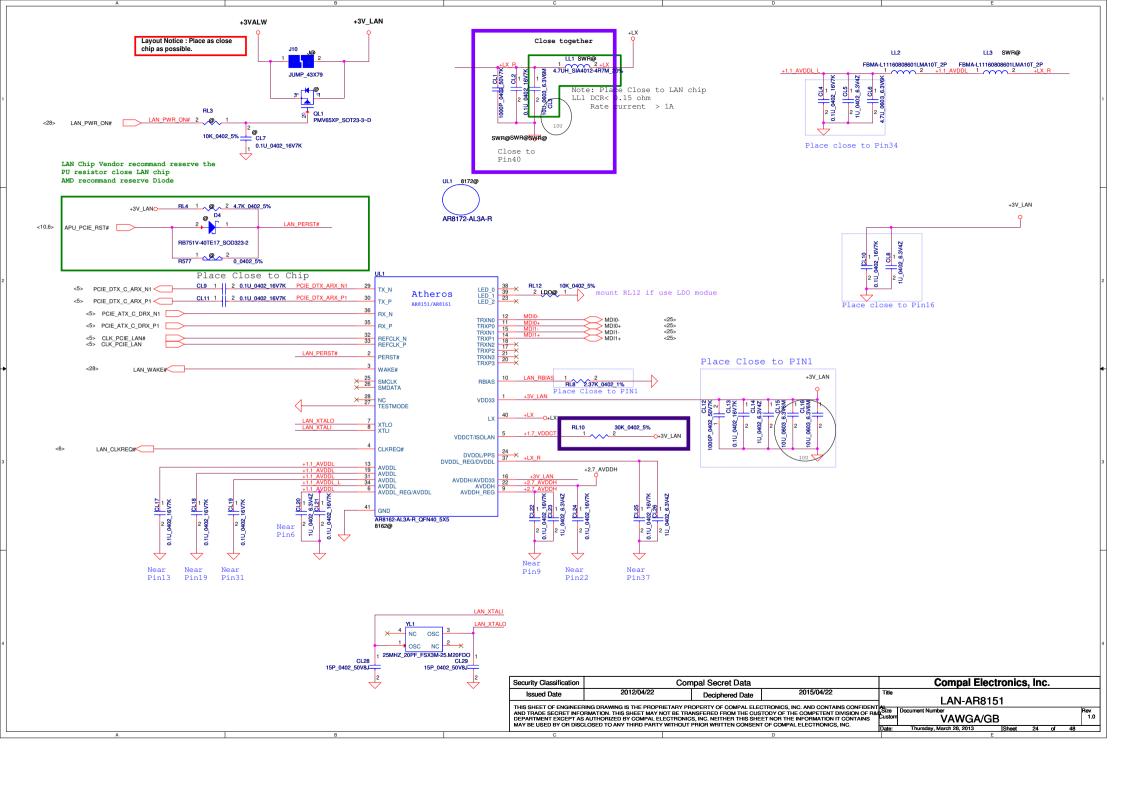


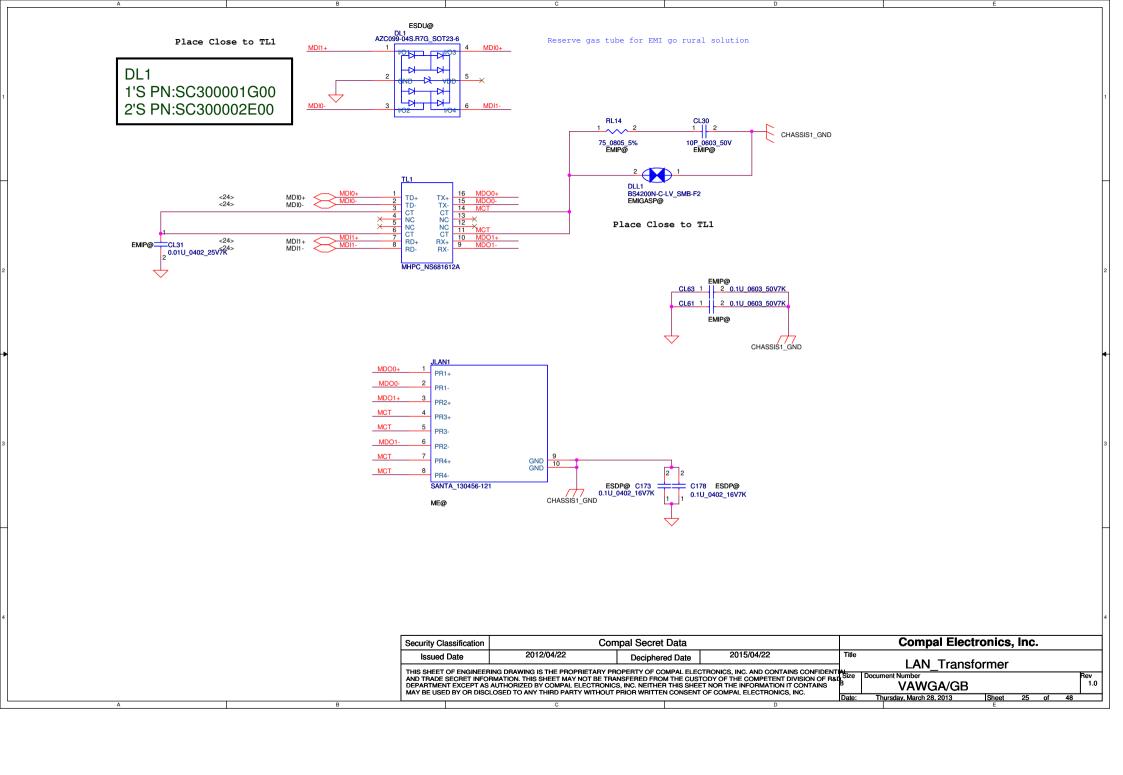


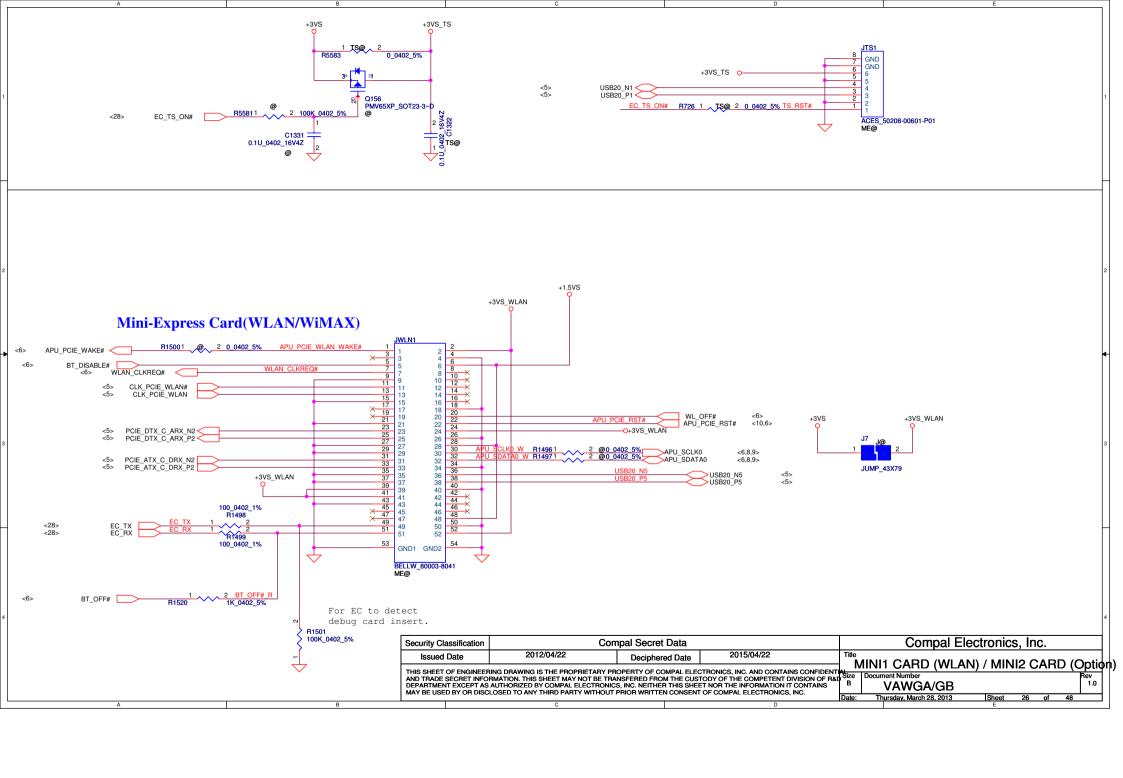


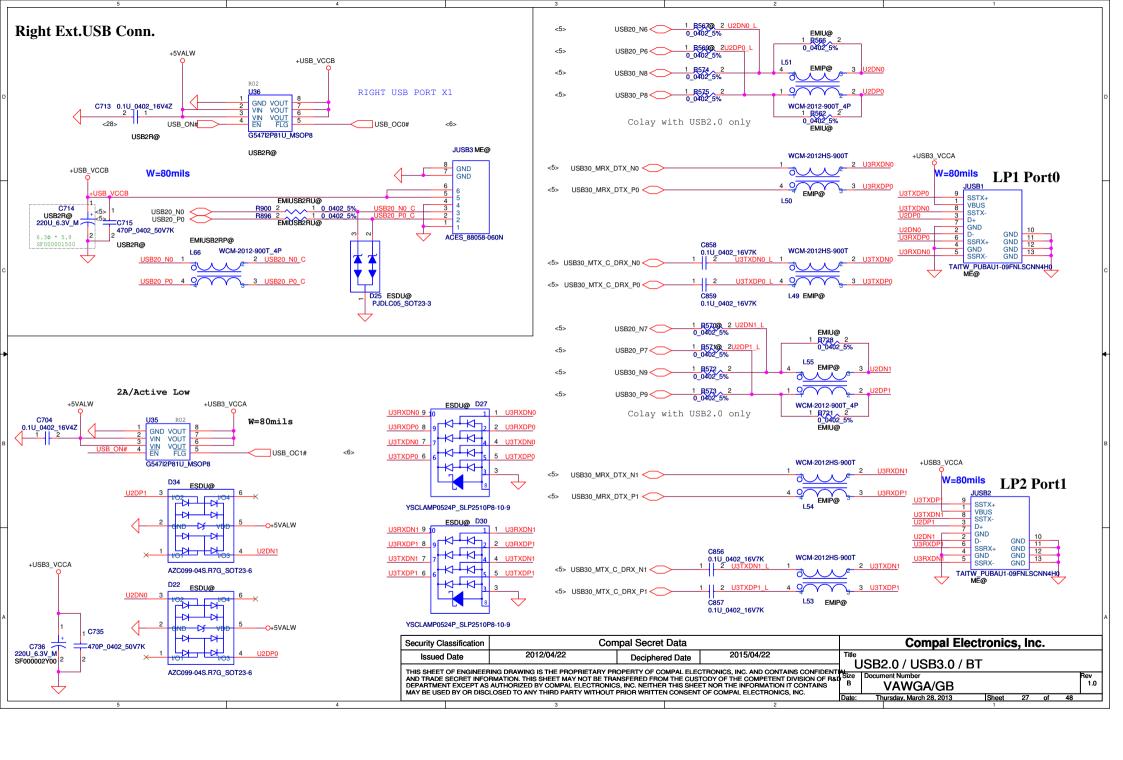


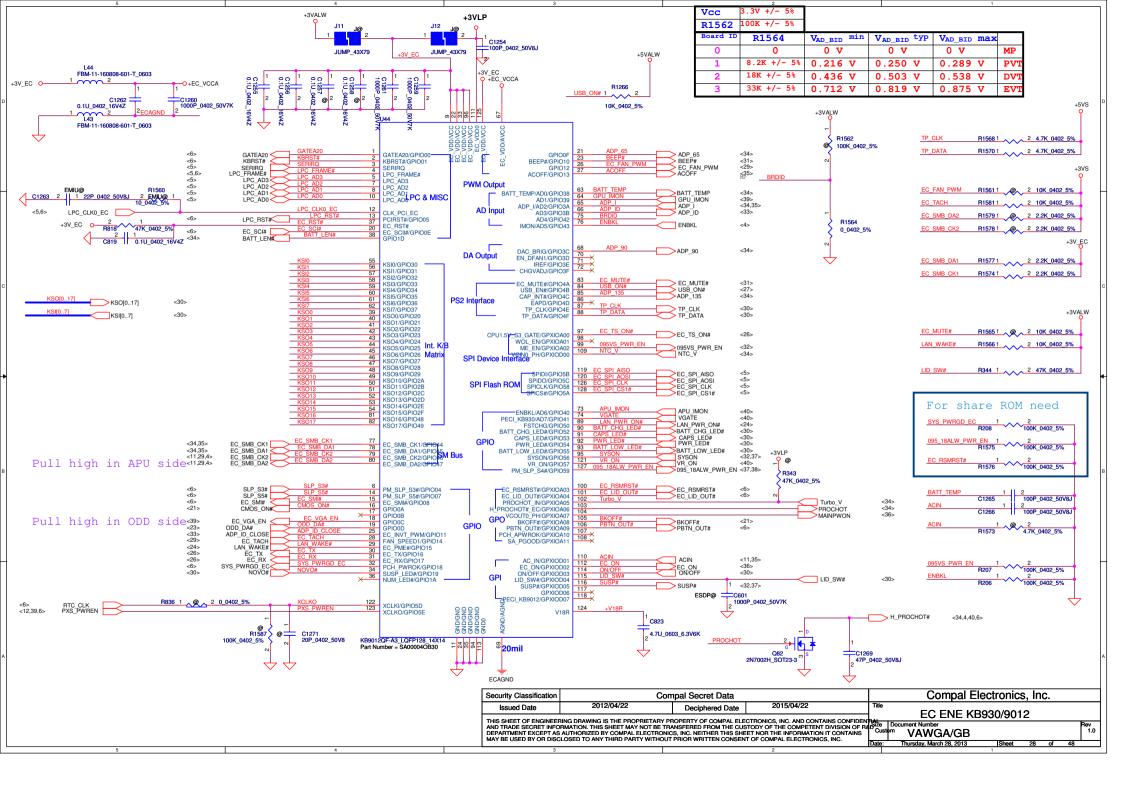


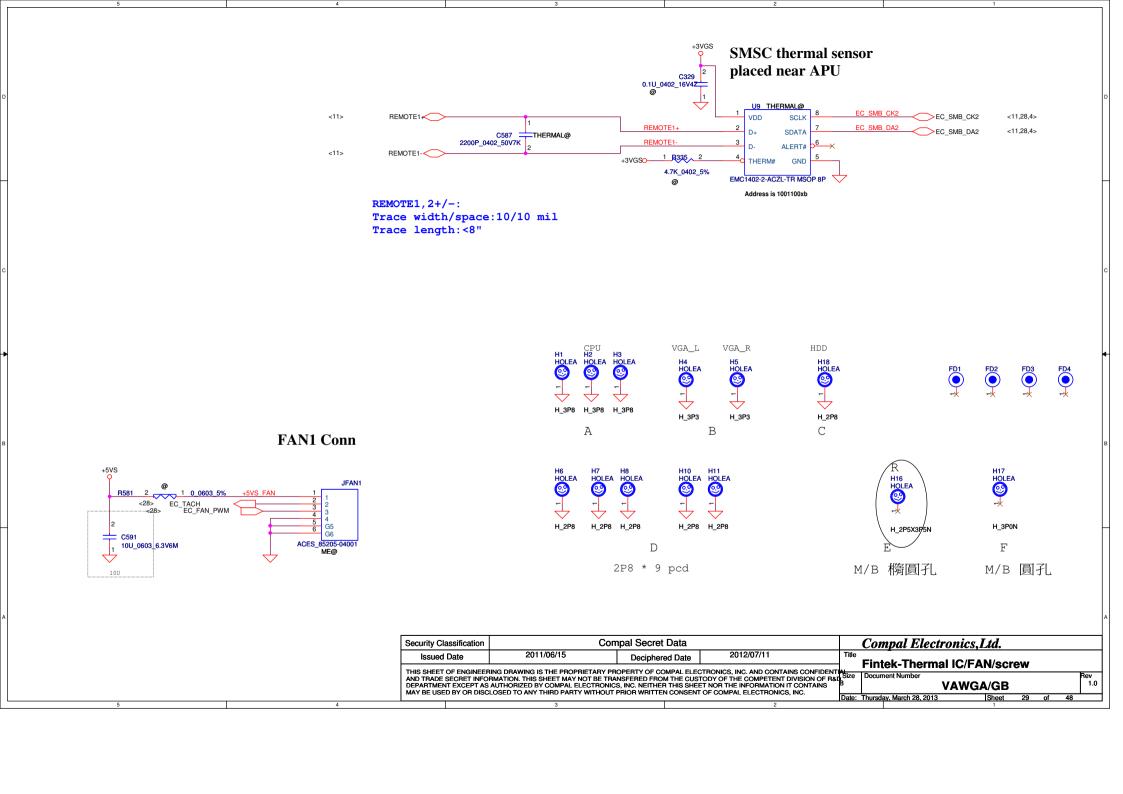


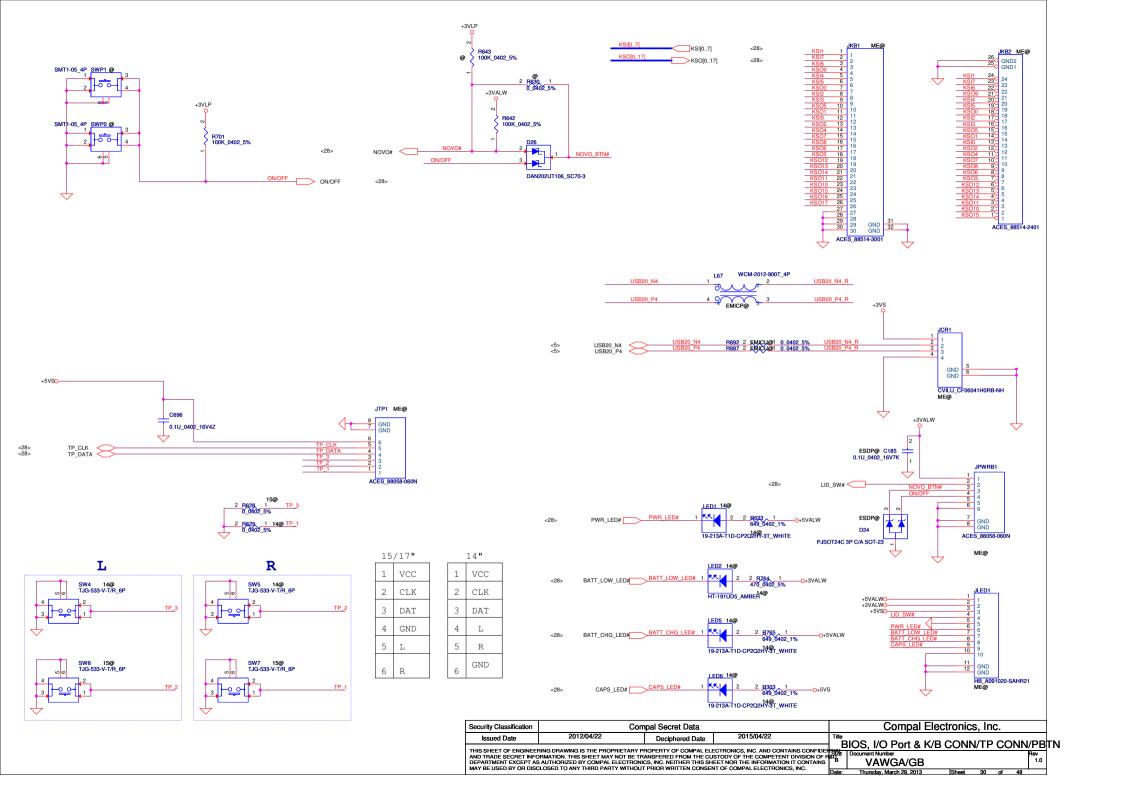


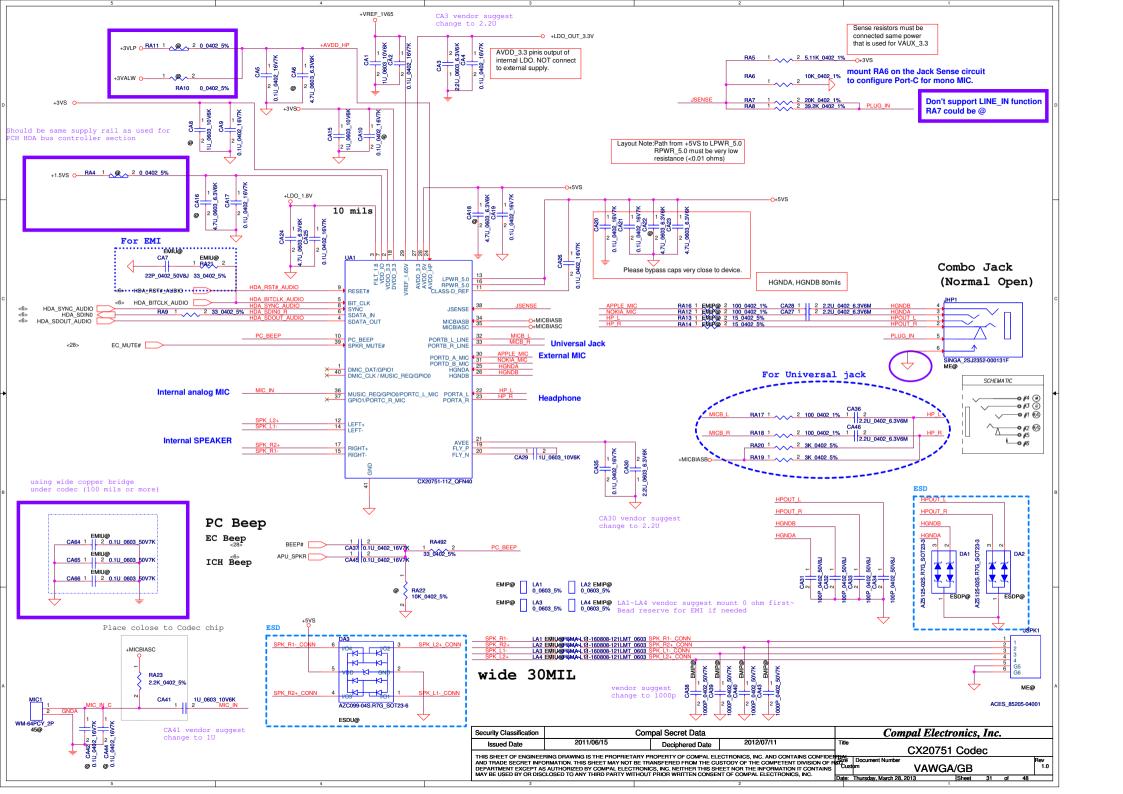


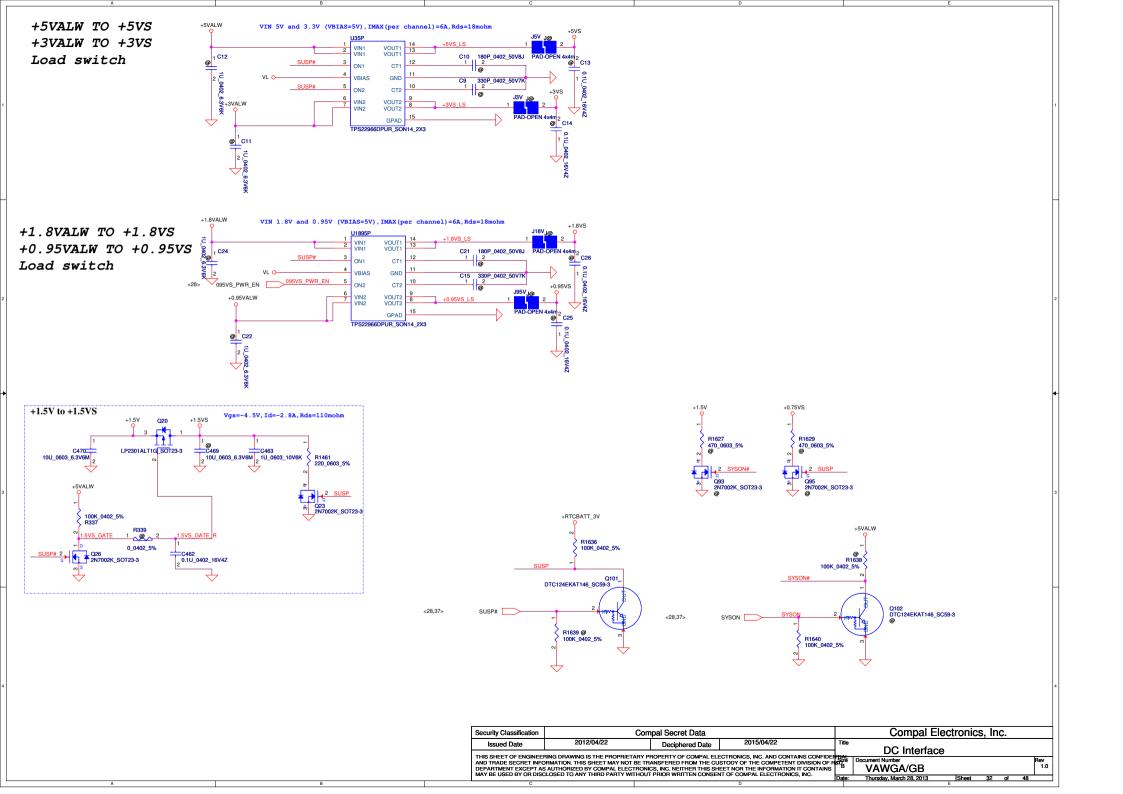


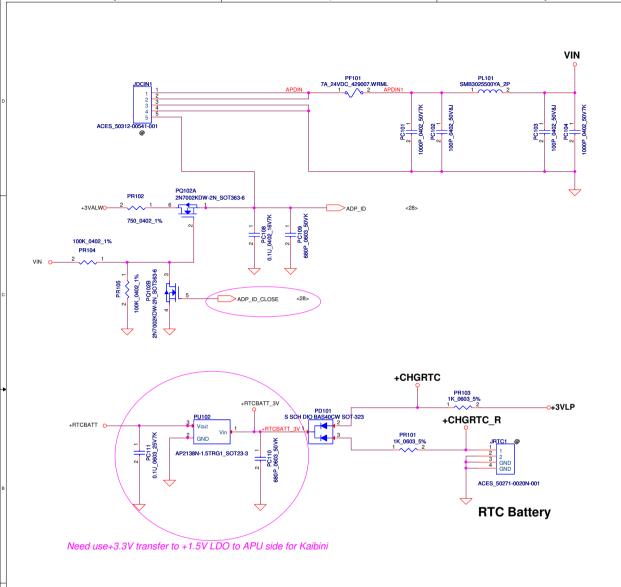


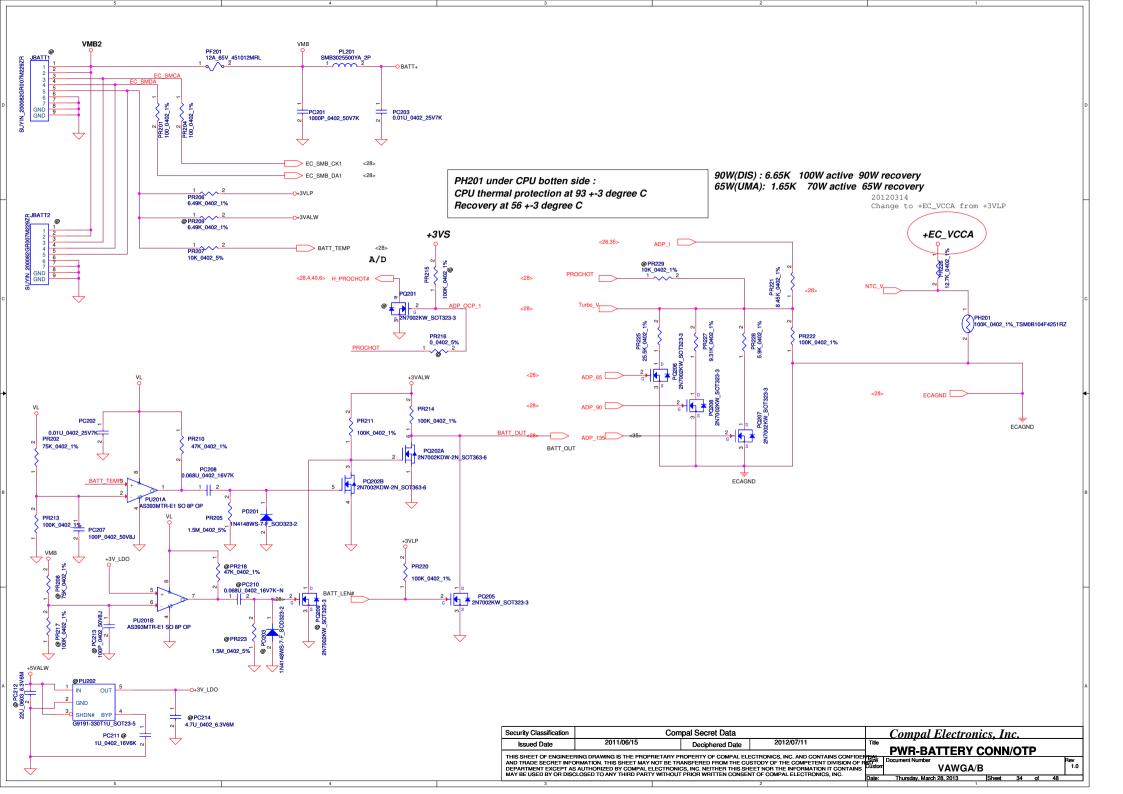


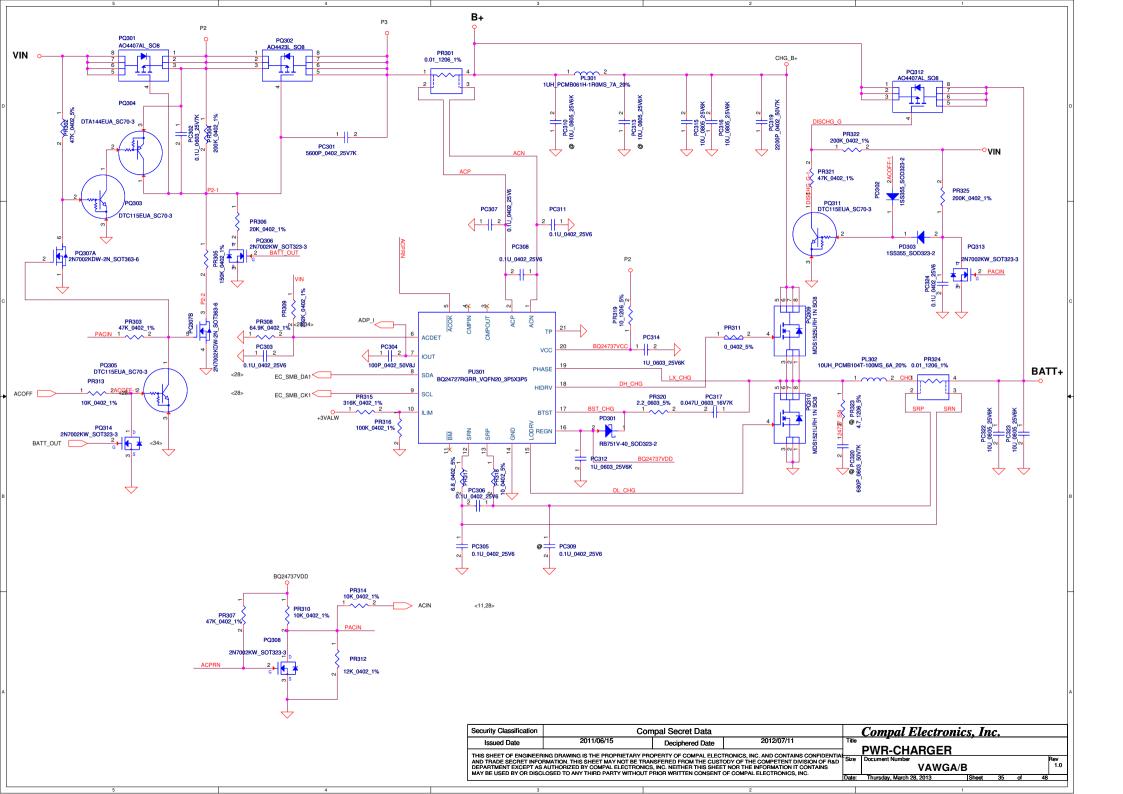


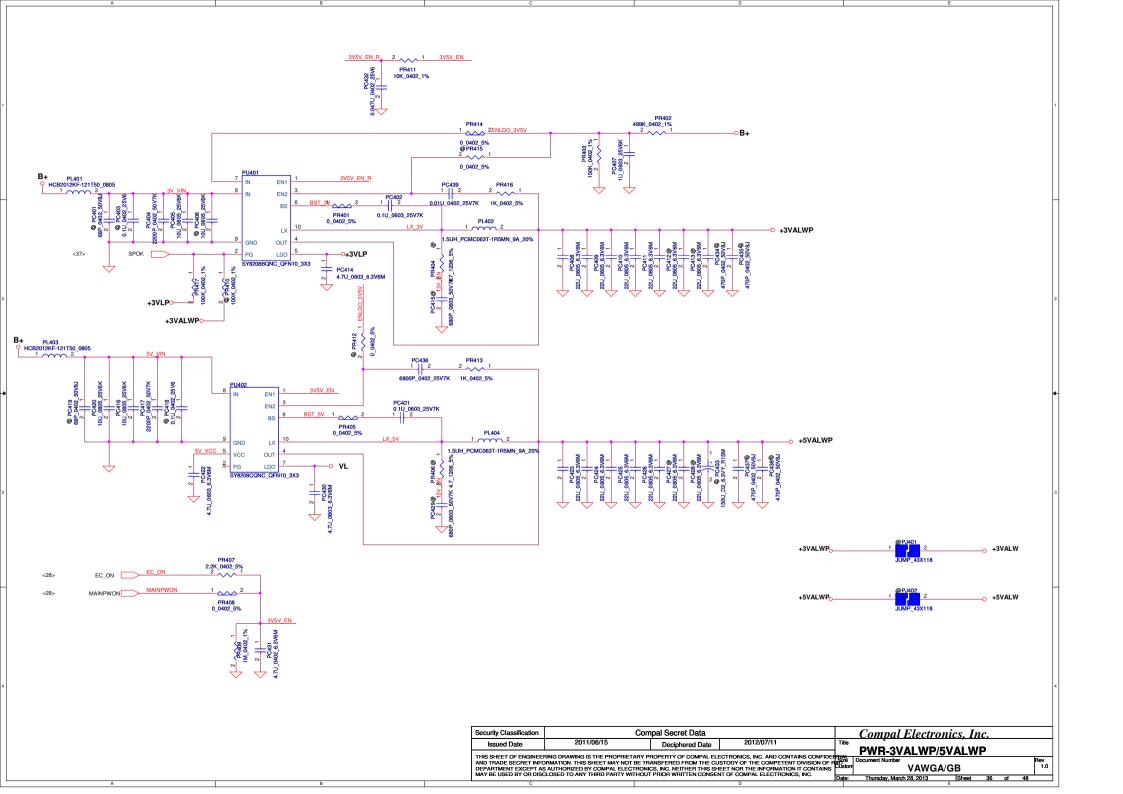


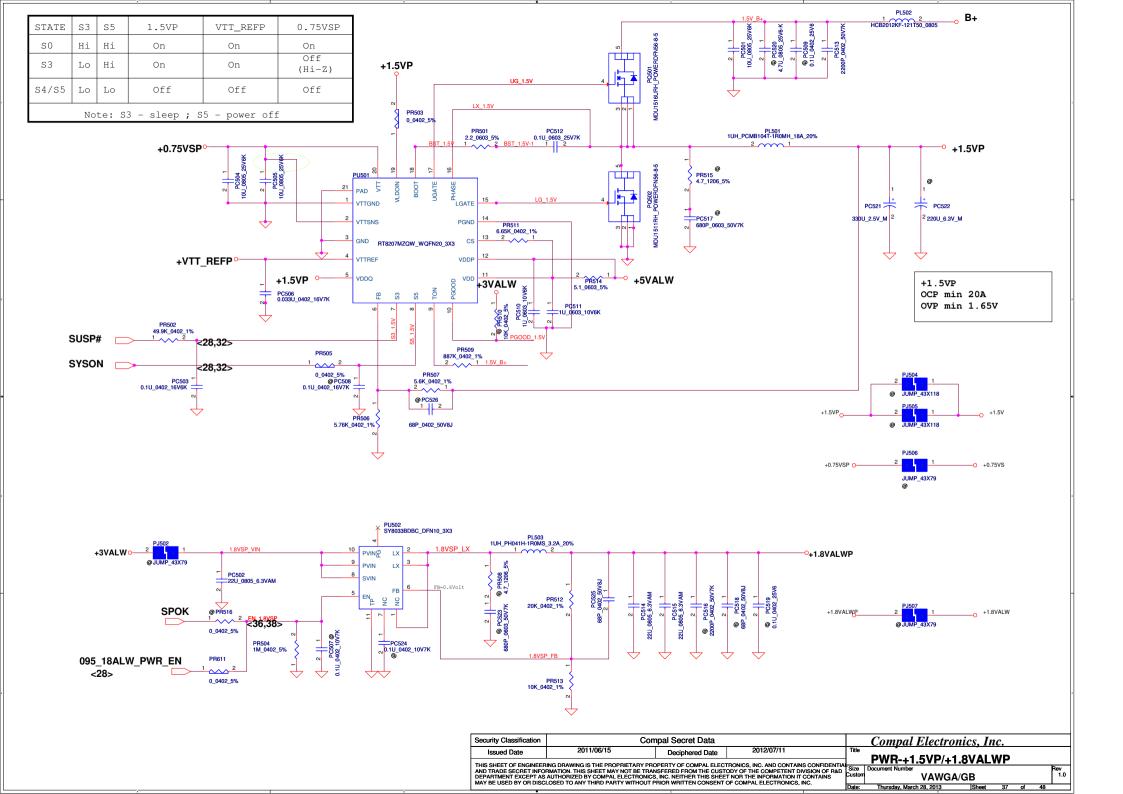


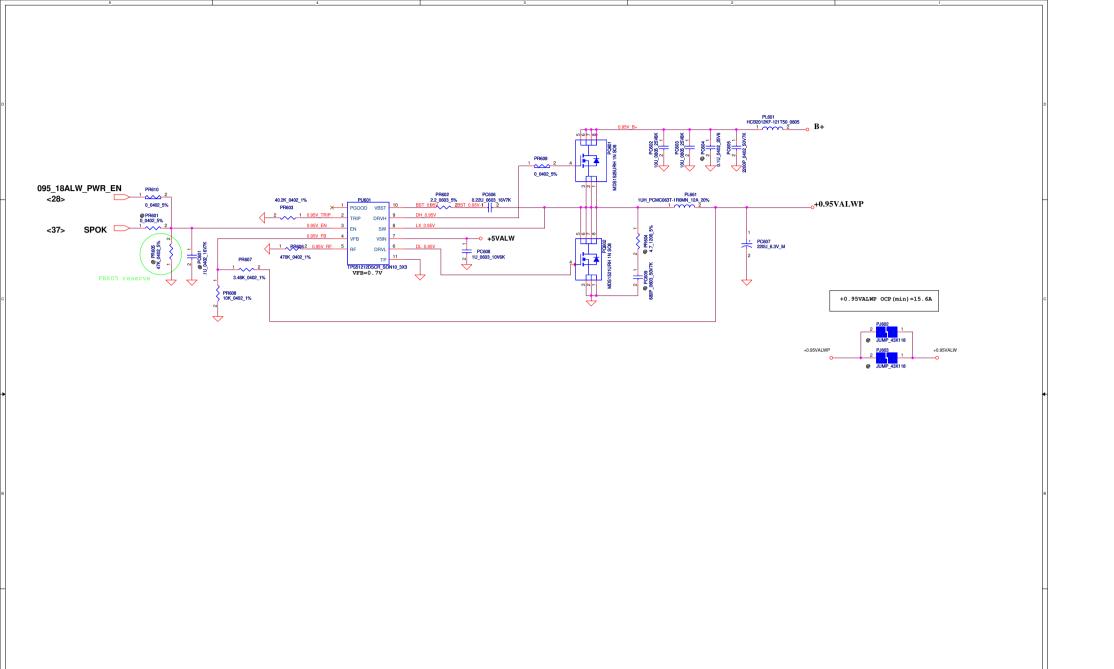


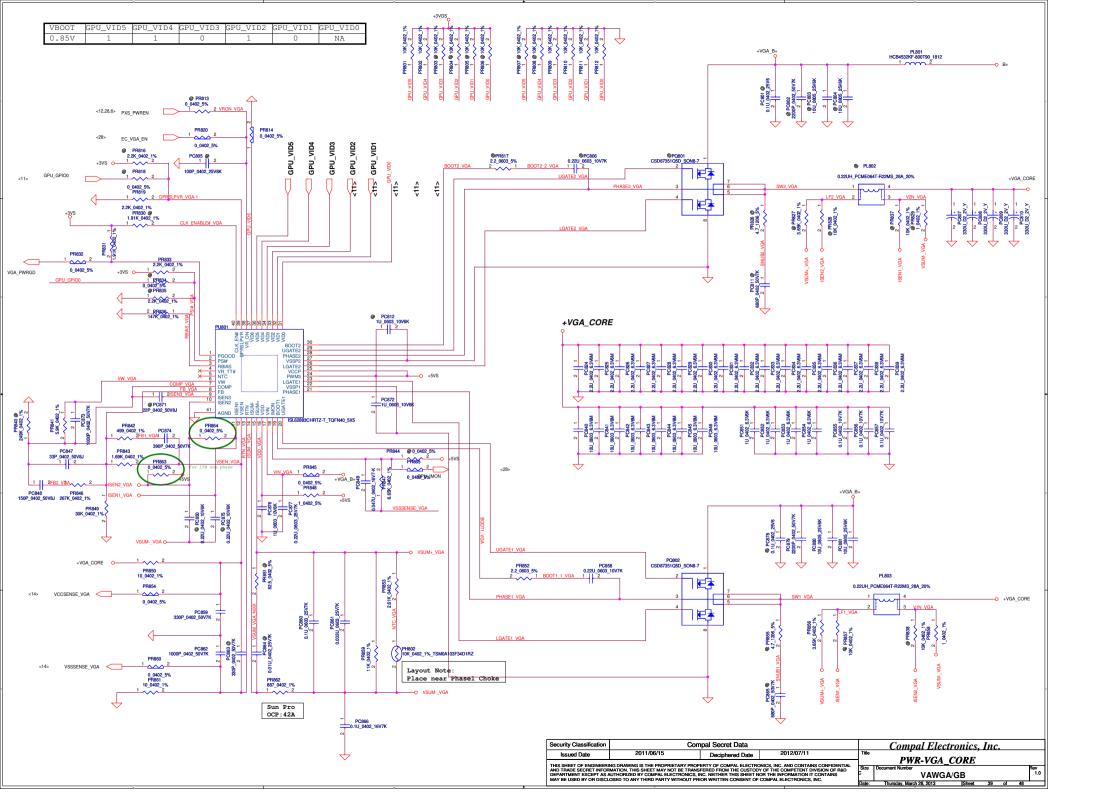


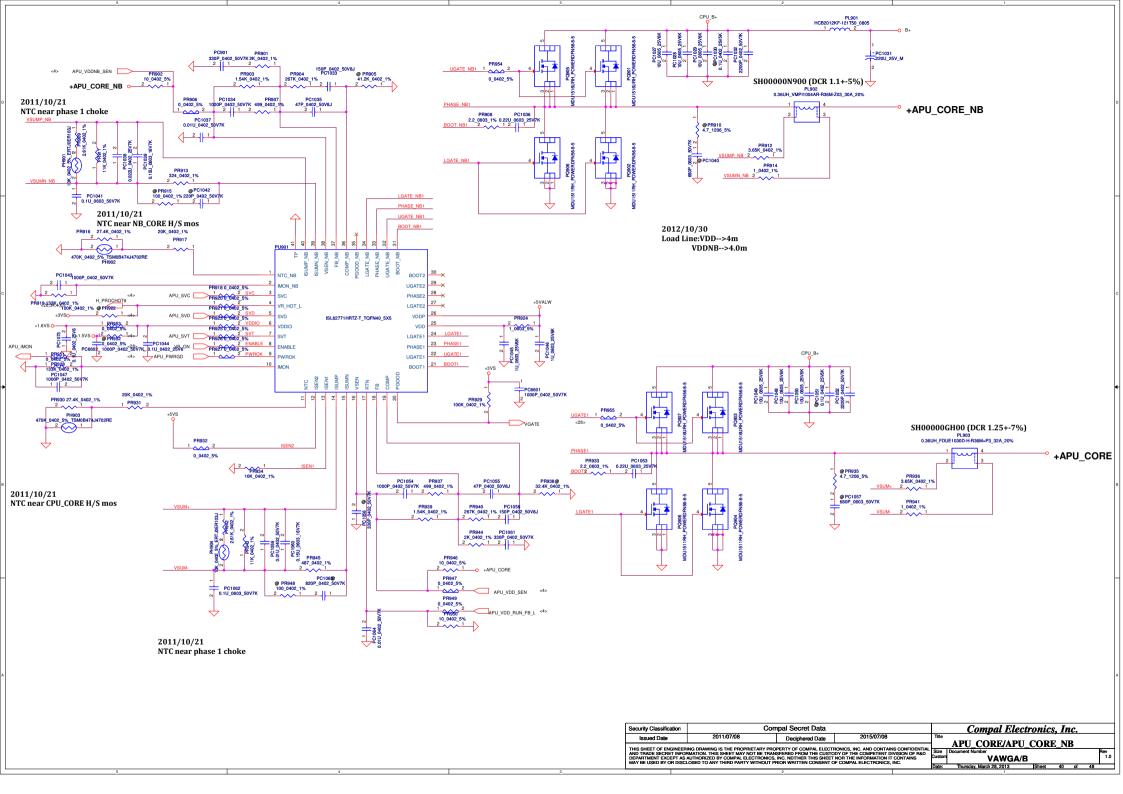


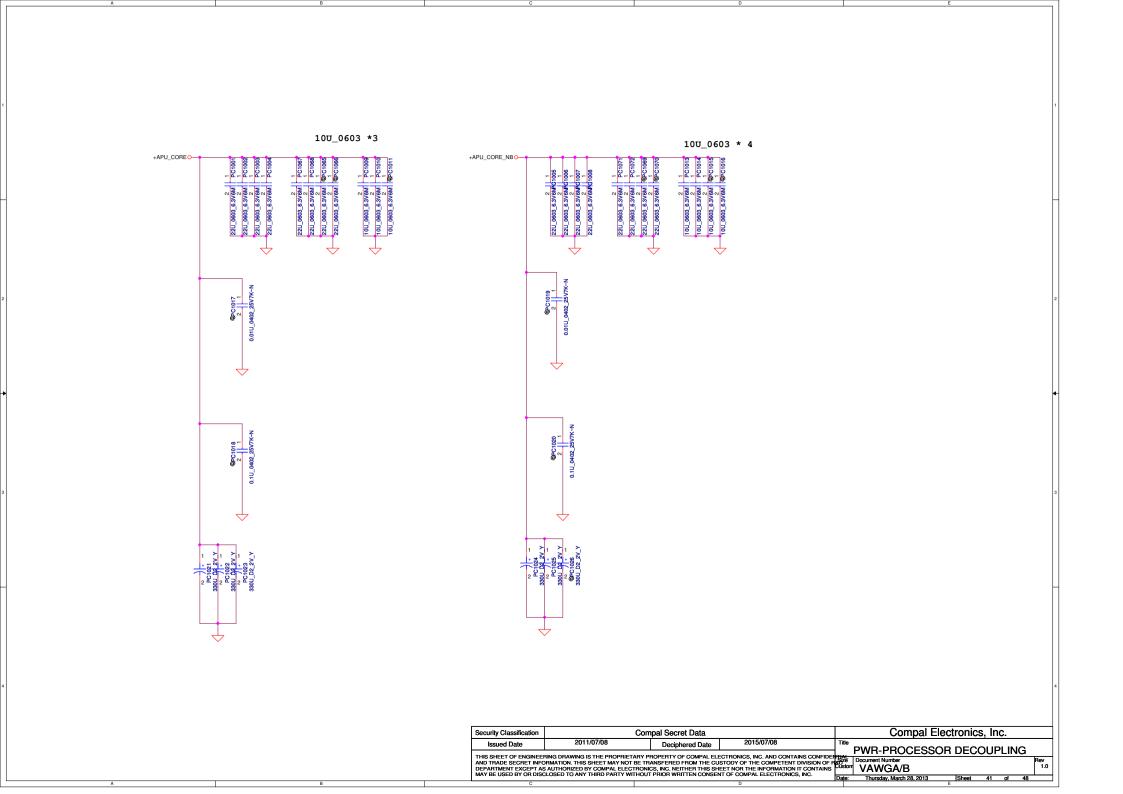












Page 1 of 1 for PWR Version change list (P.I.R. List) Reason for change PG# Item Modify List Date Phase 

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# Version change list (P.I.R. List)

## Page 1 of 1 for HW

Item	Reason for change	P <i>G</i> #	Modify List	Date	Phase
1	For share rom	28	Change SYS_PWRGD_EC from pin 86 to pin 32	12/17	DVT
2	For 095VS_PWR_EN pull down	28	Add R207	12/17	DVT
3	For VBIAS first raise up	12 <b>,</b> 32	Change U1895V, U35P, U1895P VBIAS from +5VALW to VL	12/17	DVT
4	For follow VIWGP design	27	Change JUSB3 pin define	12/18	DVT
5	For Audio Precision	31	Change CA36, CA46 from 1U to 2.2U	12/21	DVT
6	For SYS_PWRGD_EC pull down	28	Add R208	12/24	DVT
7	For share rom	28	Change R1575, R1576 to 100K	12/24	DVT
8	For reserve EC +3VL	28 05	Add J11, J12 and modify +3VALW to +3V_EC	12/24	DVT
9	For share ROM	05	modify ROM net-name & resistor value	12/24	DVT
10	For common VIWGP design	22	modify R106, R107 to 22ohm	12/24	DVT
11	For power S3 reduction	28	Change EC_INVT_PWM to ADP_ID_CLOSE	12/25	DVT
12	For common VIWGP design	23	Change JODD1 symbol	12/27	DVT
13	For reserve wake on wlan function	26	Add R1500	12/27	DVT
14	For 1.5VS discharge	32	Change R339 to Oohm, mount Q23 & R1461	12/29	DVT
15	For AMD suggest	4	Change R576 to Oohm	12/29	DVT
16	For VGA sequence	12	Delete R123 & C40, change C28, C27 to 2200P	12/29	DVT
17	For +3VALW APU Power Consumption	7	Add R582	01/03	DVT
18	For ESD request	22 28 40	Add C600, C601, PC6601, PC6602	01/03	DVT
19	For no support DC wake & LID function	28	Pull high only SMB & RST use +3V_EC, other use +3VALW	01/04	DVT
20	For reserve cost down experiment	30	Add R630, R643	01/04	DVT
21	For Common VIWGP	30	Change SW4,SW5,SW6,SW7 footprint	01/04	DVT
22	For instant plug/unplug AC has beep sound	31	@RA22	01/04	DVT
23	For Crystal Capactance fine tune	5 6 12	Modify C794,C795,C682,C686,CV36,CV37 value	01/09	DVT

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# Version change list (P.I.R. List)

Page 1 of 1 for HW

			I OI: FIV	TOP HW		
Item	Reason for change	PG#	Modify List	Date	Phase	
1	For EMI request	30	Change L67 to EMICP@, Change R692,R687 to EMICU@	02/02	PVT	
2	For Share ROM recoverable solution as original method	05	Add RP12	02/02	PVT	
3	For BIOS post time	06	Pull high PXS_PWREN to +3VS by RP14	02/02	PVT	
4	For ZiZi noise	31	Change AVDD_HP from +3VS to +3VLP	02/02	PVT	
5	For follow KABINI latest CRB	04	@ R576,C164,C342	02/02	PVT	
6	For APU control PWM only	21	Delete R1465	02/02	PVT	
7	For Corret Net-name to prevet confuse	04 21	Change TL_INVT_PWM, TL_ENVDD to APU_INVT_PWM, APU_ENVDD	02/02	PVT	
8	For Reserve DDC CLK DATA pull high	22	Add R693, R697	02/02	PVT	
9	For Common Intel project	30	Change R623,R765,R303 to 620ohm	02/02	PVT	
10	For Common Intel project	23	Reserve R551	02/02	PVT	
11	For reduce BOM	31	Delete RA3, and Change RA4 to short-pad	02/05	PVT	
12	For reduce BOM	26	Change R1498,R1499 from 0 ohm to 100 ohm	02/05	PVT	
13	For reduce BOM	11 12 13 14	Change RV43,LV1,LV2,LV3,LV4,LV5,LV6,RV16,RV17,LV7,LV8,LV9,LV10 to short-pad	02/05	PVT	
14	For better location	14 18 19	CV72 <-> CV171 ; CV60 <-> CV70 ; CV154 <-> CV191	02/05	PVT	
15	For reduce BOM	21	Change R1463 from 0 ohm to short-pad	02/06	PVT	
16	For better audio precision performance	31	Change CA27,CA28 from 1U to 2.2U	02/08	PVT	
17	For reduce BOM & layout concern	07	Delete C195	02/16	PVT	
18	For test point request	22	Add T49, T58 on JCRT1	02/18	PVT	
19	For ESD request	25	Add C173, C178	02/18	PVT	
20	For reduce BOM	05	Change R112, R115, R116, R119, R125, R126 to short-pad	02/18	PVT	
21	For Crystal timming	06	Change C682 from 18P to 22P	02/20	PVT	
22	For ESD request	30	Change D24 from ESDU@ to ESDP@, Part number from SCA00000E00 to SCA00001G00	02/23	PVT	
23	For EMI request	21 27 30	Change L58,L51,L55,L66,L67 from SM070000K00 to SM070000Z00	02/23	PVT	

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# Version change list (P.I.R. List)

## Page 1 of 1 for PWR

Item	Reason for change	PG#	Modify List	Date	Phase
1	For Common Intel project	30	Change R623,R765,R303 to 649ohm	03/05	PreMP
2	For VGA Clock Request	06	Reserve R578,R689	03/05	PreMP
3	For Reduce BOM	05	Change R103, R104 to short-pad	03/11	PreMP
4	For Reduce BOM	21	Change R696, R695, R813 to short-pad	03/11	PreMP
5	For Reduce BOM	23	Change R550 to short-pad	03/11	PreMP
6	For Reduce BOM	28	Change R1564 to short-pad	03/11	PreMP
7	For Reduce BOM	29	Change R581 to short-pad	03/11	PreMP
8	For Reduce BOM	31	Change RA11 to short-pad	03/11	PreMP
9	For Reduce BOM	32	Change R339 to short-pad	03/11	PreMP
10	For Reduce BOM	06	Change R121 to short-pad	03/11	PreMP
11	For Reduce BOM	07	Change R582 to short-pad	03/11	PreMP
12	For ESD require	30	Add C185	03/25	PreMP
13	For Module Design	22	Change R693, R697 from 10k to 4.7k	03/25	PreMP
14	For ESD require	04	Add C195	03/26	PreMP
15	For Reduce BOM	04	@ RP11	03/26	PreMP
16	For Board ID	28	@ R1562 and change R1564 to Oohm	03/28	PreMP
17					

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#### Mars XT VRAM STRAP

Vendor	PS_3[2]	PS_3[1]	PS_3[0]	R_pu	R_pd
K4W2G1646E-BC1A SA000068U00	0	0	0	RV20 NC	<b>RV27</b> 4.75K
MT41J128M16JT-093G:K SA000067500	0	0	1	<b>RV20</b> 8.45K	<b>RV27</b> 2K
H5TQ2G63DFR-N0C SA000065300	0	1	0	RV20 4.53K	<b>RV27</b> 2K
H5TC2G63FFR-11C SA00006H400	1	0	0	RV20 4.53K	<b>RV27</b> 4.99K
K4W1G1646G-BC11 SA00004GS00	0	1	1	RV20 6.98K	RV27 4.99K
H5TQ1G63EFR-11C SA000041SB0	1	1	1	RV20 4.75K	RV27 NC

MS2G@ X7646738L01 MM2G@ X7646738L02 OLDMH2G@ X7646738L09 NEWMH2G@ X7646738L03 MS1G@ X7646738L03 MH1G@ X7646738L04

### **SUN PRO VRAM STRAP**

Vendor	PS_3[2]	PS_3[1]	PS_3[0]	R_pu	R_pd
- K4W4G1646B-HC11 SA000068R00	0	0	0	RV20 NC	<b>RV27</b> 4.75K
MT41K256M16HA-107G:E SA000065D00	0	0	1	<b>RV20</b> 8.45K	<b>RV27</b> 2K
H5TQ4G63MFR-11C SA00006DG00	0	1	0	RV20 4.53K	<b>RV27</b> 2K
K4W2G1646E-BC1A SA000068U00	0	1	1	RV20 6.98K	RV27 4.99K
MT41J128M16JT-093G:K SA000067500	1	1	0	RV20 3.4K	RV27 10K
H5TC2G63FFR-11C SA00006H400	1	0	0	RV20 4.53K	RV27 4.99K
- H5TQ2G63DFR-N0C SA000065300	1	1	1	RV20 4.75K	RV27 NC

 SS2G@
 X7646738L05

 SM2G@
 X7646738L06

 SH2G@
 TBD

 SS1G@
 X7646738L07

 SM1G@
 X7646738L08

 NEWSH1G@
 X7646738L13

 OLDSH1G@
 X7647538L01

#### Power-Up/Down Sequence

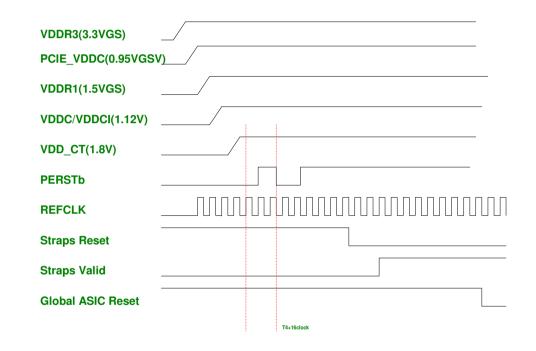
"Mars" has the following requirements with regards to power-supply sequencing to avoid damaging the ASIC:

• All the ASIC supplies must reach their respective nominal voltages within 20 ms of the start of the ramp-up sequence, though a shorter ramp-up duration is preferred. The maximum slew rate on all rails is  $50~\text{mV/}\mu\text{s}$ .

• The external pull ups on the DDC/AUX signals (if applicable) should ramp up before or after both VDDC and VDD\_CT have ramped up.

• VDDC and VDD\_CT should not ramp up simultaneously. For example, VDDC should reach 90% before VDD\_CT starts to ramp up (or vice versa).

· For power down, reversing the ramp-up sequence is recommended.



Security Classification	Com	Compal Secret Data 2011/06/15 Parishard Data 2012/07/11			Compal Electronics, Inc.		
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